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## Introduction

The research of habitable planet is one of the major concerns of human beings. Indeed, this discovery, in addition to give hope of locating another species, would bring solutions to overpopulation. According to scientists, the main criterion for life is water. Since the properties of celestial bodies are disparate, a habitable zone was defined, considering that water can only exist at a specific range of temperature. If the temperature of the planet is too low, the water will freeze and conversely, it will evaporate if the temperature is too warm. The habitable zone is not fixed; it moves with the evolution of the sun. Mars is thought to have belonged to the zone once, due to its most hospitable climate after Earth. For a matter of fact, NASA's Mars Reconnaissance Orbiter has recently provided a strong evidence of water currently flowing on the Red Planet. It may then be possible to live on Mars and that is the aim of Mars one project: send a colony over there. The terraforming, which would change characteristics of Mars to make it suitable for humans, is also worth considering before colonization. In order to do so, scientists need to learn more about the features of the planet. Orbiters and rovers are already scanning mars surface and soil. Nevertheless, they lack the depth information, only equipped of Two Dimensional (2D) cameras. Their three dimensional (3D) scans have permitted to acquire it and to print a Martian meteorite on Earth in 2014. This information is useful for a better understanding of the rocks properties but that is not enough. Some missing data have delayed the 3D print. It could be interesting to provide to scientists a real time 3D map of a selected rock. It would be easier to study stones but the map could also help the robot to stabilize. With wind and an uneven ground, the rover is liable to move. The pattern recognition of a rock would be more robust by adding a 3D map. Samples could be collected being sure that the robot has taken the right piece.

Furthermore, the 3D map could have several other applications. The features of the Martian soil acquired by the orbiting satellites are not exhaustive and lack of accuracy. Thus, applied to the area in front of the robot, the 3D map could detect new obstacles and update in real time the available map to distinguish modifications of the ground. It could also permit spacecrafts to determine a flat area to land in real time by analyzing the surface of the planet from space and during the descent. Moreover, the 3D map has other applications in completely different fields. Indeed, this technical can found, as example, in

- video games, with environment recordings for real time augmented reality gaming
- medicine, with skin surface measurement or skin roughness measurement

- cosmetic, with wrinkle measurement
- industry, with 3D-automated optical inspection, volume measurement or Classification of grinding materials and tools

However, the 3D mapping is not much used and is still improving. In this context, designing a system capable of carrying out a 3D map of a Martian rock would be profitable for future research. This is the purpose of this project, undertaken during the Image Analysis with Microcomputer course, under the supervision of Alessandro Massaro. Combining image and scene analysis, programming and robotics seems relevant for learning to work as an engineer.

This report is intended to our fellow students. The first part will bring additional knowledge required to understand the next developments. The design of the system is described in the next section, followed by its verification. To end, future work is addressed.

# Part 1

## Problem formulation and delimitation

### 1.1 Problem formulation

In this report, we assume that we would like to send a rover on Mars, capable of communicating with Earth. Self-powered by solar panels, it will land at latitude  $50^\circ$  where it could get enough sunlight to recharge its lithium batteries. It is provided with an arm whose hand is replaced with a camera (see figure 1.1). The latter will be used by scientists to observe relevant rocks to study. In order to accomplish this mission, once a stone is designed, the camera must be able to keep it in focus, despite the wind, the movement of the robot or any other perturbation. This implies a real time image analysis to be able to rectify the position of the camera. As a robust method is needed to maintain the stone in front of the arm, the identification of patterns should be completed by carrying out a 3D map of the surface. A luminous source should then be added to the rover to be projected on the surface containing the rock and detected by the camera.

This luminous source must be powerful enough to outshine the sunlight during the day, notwithstanding that the energy needed to make it work has to be negligible compared to the amount provided to the rover. Moreover, the characteristics of the camera need to be perfectly adapted to Mars, as once the rover has landed on the red planet, it would be impossible to adjust it.

Will it be feasible to design such an embedded system, composed of a camera, a luminous source and algorithms, capable of keeping a rock in focus thanks to a 3D map, for an application on Mars soil?

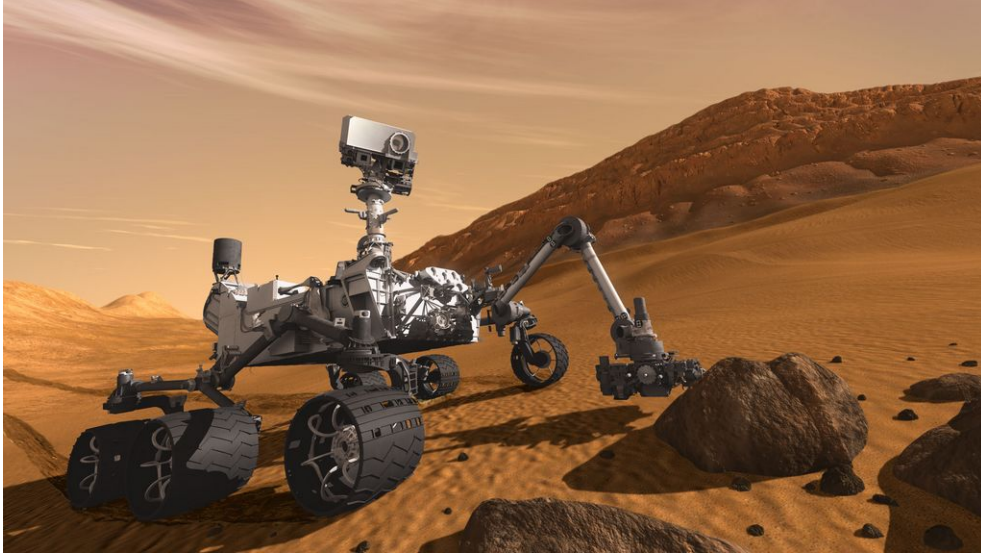


Figure 1.1: Curiosity Rover with an embedded camera on a arm [6]

## 1.2 Problem delimitation

First of all, we assume that the rover is already in front of the rock, that is to say, we do not take into account the path to go close to the target with the different potential obstacles that may be present on the way. Then, in order to design the rover's camera which will be used to study rocks and to implement a robust algorithm to carry out a 3D map of the rock's surface, different characteristics of Mars and of the target need to be specified. However, as all of them cannot be taken into account, some simplifications and choices will be assumed.

### Mars delimitation

Plenty of missions on Mars have been realized and a great deal of data has already been gathered. Nevertheless, even if some of them will be used to designed our system, others will be simplified or even ignored. The first simplification concern the atmosphere of Mars. Indeed, even if its composition is now well know, it will be assumed that the dirt on the surface Mars plus the different layers of the atmosphere absorb, or scatter, 10% of the solar energy. Moreover, the influence on the image acquisition that the dirt between the target and the camera could have will not be taken into account. The second reduction cover the temperature. Indeed, even if it can reach  $-143^{\circ}\text{C}$  during winter,  $27^{\circ}\text{C}$  during summer and have around  $60^{\circ}\text{C}$  variations between daytime and nighttime[7], we will assume that the CCD sensor works well all the time.

### Target delimitation

Regarding the target, that is to say the part of the rock being studied, it is sup-

posed to :

- be vertical;
- not exceed 2\*2 meters
- have an area between 0.1 and 1 square meters;
- have a relief less than meters.

### Camera delimitation

Then, regarding the camera which is designed during this study, it is presumed to :

- be between one and two meters far from the target;
- be right in front of the target, that is to say that the angle between the normal of the target's surface and the focal axis of the camera is  $0^\circ$ ;
- be able to capture the image of a target of 2 meters height maximum.

The different characteristics of target and the camera are represented figure 1.2

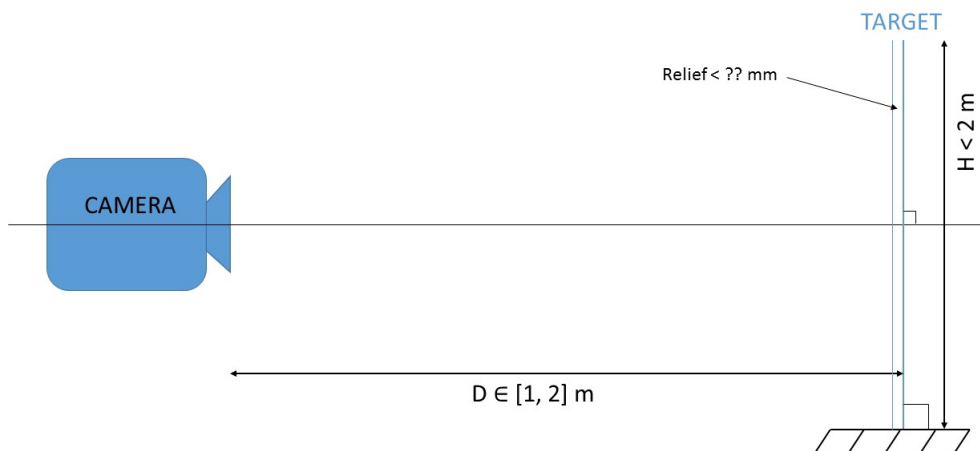


Figure 1.2: Schema of the scene

Finally, the last assumption is that the wave length taken into account is from 400 to 800 *nm*. Indeed, the first reason is that the CCD sensor chosen (see part ??) works with this range of wave length. Moreover, this range corresponds almost to the visible spectrum (380 - 750 *nm*), with which the 3D algorithm works, and as Mars has a reddish color and a lot of infrared, the spectrum is expanded to 800 *nm*.



## Part 2

# Theory Section

### 2.1 Mars Features

Mars, the fourth planet from the Sun (1.3814 to 1.6660 AU) is the second smallest planet of the the Solar System (its radius is 3389.5 km). Known as the “Red Planet” because of the amount of iron oxide on its surface, it has an orbital period of 668.6 sols (Mars’ solar day), that is to say 687 days, with an average day length of 24h37m.

#### 2.1.1 Atmosphere of Mars

Because of its thin atmosphere, Mars has surface features which present analogies with both Moon, through the impact craters, and Earth, with volcanoes, deserts, polar ice caps. It is mainly composed of carbon dioxide  $\text{CO}_2$  (96,0 %  $\pm$  0,7 %), argon  $\text{Ar}$  (1,93 %  $\pm$  0,01 %) and oxygen  $\text{O}_2$  (0,145 %  $\pm$  0,009 %). As the gravity of Mars is low, the height of the atmosphere is 11 km, more than one and a half times higher than the Earth’s one (7 km). Moreover, due to this low gravity, the wind can disrupt a rover easier than on Earth and a large amount of suspended dust is perpetually present at the surface.

Regarding the dust, of which the particles have a mean diameter of  $1,5\mu\text{m}$ , is continually injected into the atmosphere by wind or dust devils (a 12 km high one can be seen 12 Figure 2.1). Such eddies are far from anecdotal because they bring dust to significant volumes of the atmosphere. Even if the amount of dust is never very massive, it can be lifted by winds slower than  $2\text{ m/s}$  and maintained indefinitely by wind of only  $0,8\text{ m/s}$ .

Moreover, regarding the wind on Mars, in low altitudes, the Hadley circulation<sup>1</sup> dominate and is almost the same process which, on Earth, generate the Trade winds. In high altitudes, a battery of areas of high and low pressure,

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<sup>1</sup>movement on a planetary level of the layers of gases surrounding the planet



Figure 2.1: Dust Devil. Mars Reconnaissance Orbiter, made by HiRISE on Feb. 16, 2012

named baroclinic pressure waves<sup>2</sup>, dominates the weather. The Mars wind lift a large amount of dust and can even trigger huge dust storms which can affect the whole atmosphere (see Figure 2.2). Cyclonic storms can also appear on Mars. Indeed, cyclones similar to the ones of Earth tend to create during summer in the northern hemisphere but only in high latitudes.



Figure 2.2: Two views of Mars with spatial telescope Hubble before and after the big dust storm in 2001

<sup>2</sup>In meteorology a baroclinic atmosphere is one for which the density depends on both the temperature and the pressure

### 2.1.2 Climate of Mars

Because of its distance to the Sun bigger than the one of Earth, Mars receives less solar energy 3.1.5. Additionally, as its atmosphere is thinner, there is only a negligible greenhouse effect, and hence the average temperature is around  $-63^{\circ}\text{C}$  on the surface of Mars with wide variations between daylight and night.

Then, the obliquity of Mars is close to the one of Earth (respectively  $25,19^{\circ}$  and  $23,44^{\circ}$ ) but the eccentricity of Mars is bigger (0,09332 against 0,01671 for Earth) which means that, if Mars has similar seasons to Earth, they have different intensity and duration during the martian year. Thus, the northern hemisphere has seasons less pronounced than the southern hemisphere because its aphelion is at the end of spring and its perihelion at the end of autumn. Thus, there are short and soft winters and long and fresh summers in the northern hemisphere. On the opposite, the southern hemisphere has very pronounced seasons with long and cold winters and short and warmer summers than in the northern hemisphere. That is why there are higher temperature differences in the south.

### 2.1.3 Albedo

Mars surface is covered by sand and volcanic rocks. The first purpose of this project is to allow scientists to examine these rocks through the camera. To achieve it, it is needed to know their characteristics, especially their albedo. As a reminder, the albedo is the fraction of incident light which is reflected from a surface. We can assume that the power reflection of Martian rocks is the same than on Earth. Then, to cover a wide range of rocks, the albedos of a black and of a white stone would be considered. Charcoal, as a dark rock, is a powerful absorber of the sun radiation, with an albedo around 0.05. On the contrary, chalks are poor absorbers and their albedo reach 0.45 according to [4]. In the following parts of the report, it will be taken for granted that Martian rocks have an albedo between 5 and 45%.

## 2.2 Artificial Light Source

In order to carry out a 3D mapping of the target, the system needs a light source to project points which will be used by the 3D mapping algorithm. In this section, the source of light will be designed.

### 2.2.1 Design of the Light Source

First of all, the green has been chosen as color of the light source. Indeed, in order to detect easily the points projected on the target, a distinctive color should be used. As we can see figure 2.3, the CCD selected for the camera has the best quantum efficiency for a wavelength around  $510\text{ nm}$ , which means that the green is the color that is the best recorded by the camera. Secondly, as the surface on Mars is mainly orange, red and brown, this color should stand out.

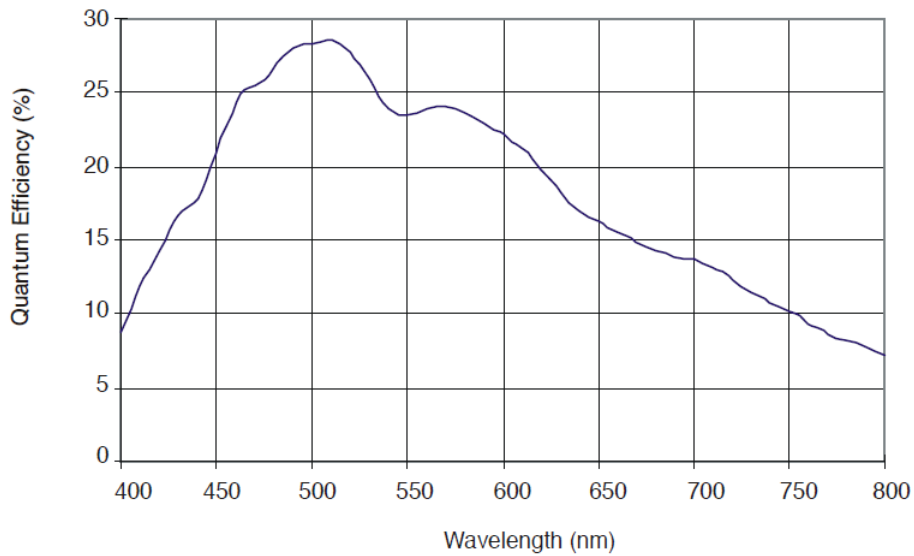


Figure 2.3: Quantum efficiency versus wavelength of the CCD

Then, as only  $300\text{ mW}$  are available to aliment the light source and a lot of lightning energy is needed to outshine the sunlight, a LED has been chosen. Indeed, LEDs have great energy performances. The properties of the chosen LED can be seen in Annex A. Note that the use of a laser have been studied, but the energy cost would have been too expensive. Moreover, even if we cannot obtained a coherent light, as a laser do, with a LED, it is still feasible to obtain a monochromatic and directional light. Thus, we will assume that the LED can bring enough light (proof in part on Signal Noise Ratio 2.2.2). Then, as the 3D mapping algorithm needs a grid of points, the LED cannot be used in its present condition. Moreover, lot of light would be lost without an optic system. Thus, a system has been designed to concentrate the luminous beams of the LED and to transform the continuous light into a grid of point. The system uses a lens and a grid (Figure 2.4).

As the LED has a diffusion angle of  $30^\circ$  (Annex A), the lens needs to be close enough to collect all the light beams of the LED to avoid losses of energy. In order

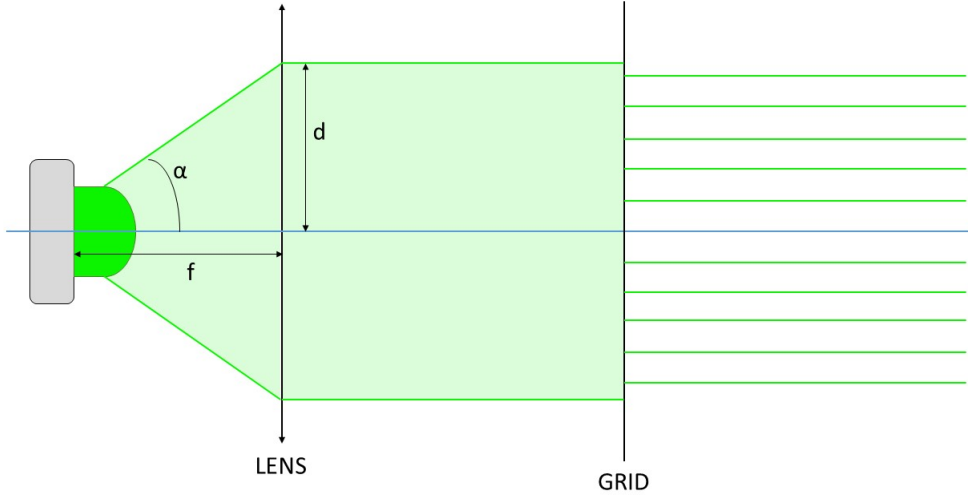


Figure 2.4: schema of the LED system

to capture as much light as possible, the diameter of the lens should follow (2.1).

$$d = f \tan \alpha \quad (2.1)$$

with

$$\alpha = \frac{30}{2} = 15^\circ, \text{ the half of the diffusion angle.}$$

$f$ , the focal length of the lens

Moreover, it should be pointed that there is a loss of energy because of the lens and the grid. We will assume that the energy loss coefficient of the lens  $LFL_{led}$  (Loss Factor Lens Led) is 0.5 and the one of the grid  $LFG_{led}$  (Loss Factor Grid Led) is 0.3.

### 2.2.2 Validation of the Light Source

In order to verify whether our light source has enough power or not to outshine the sunlight, the Signal/Noise ratio (SNR) has to be calculated (see part Signal/Noise ratio 3.1.9.3). Knowing that 100 is a really great SNR, as the SNR of images recorded with this system is [32, 348], it can be concluded that the LED can be chosen as light source. Indeed, even if 32 is a low ratio, it is only when all the different poor conditions happen in the same time and it does not happen frequently. Moreover, 100 to 347 are really high ratios that permit to have the 3D

algorithm working well. Thus, the design of the light source is validated.

## 2.3 Distance Camera-Target of One Point

Before starting to establish a whole 3D mapping, a more simple case can be studied first and it will be shown, in this section, how to determine the distance to only one point. Indeed, the distance between the camera and a point of the target can be easily determined thanks to a little bit of trigonometry.

The context of this case is simple, the camera is recording images of the target while the artificial light source is projecting a point on the last one (see figure 2.5).

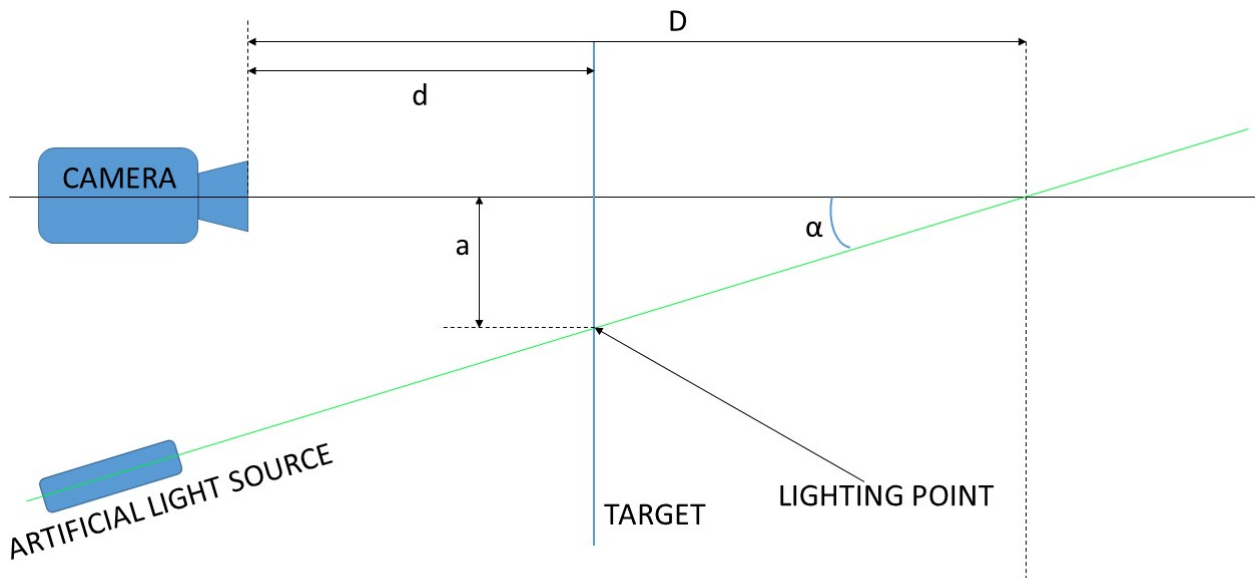


Figure 2.5: schema of the camera recording images of the target on which there is a lighting point from the artificial light source

According to the figure 2.5,

- $d$  is the distance to determine.
- $\alpha$  is the angle between the focal axis of the camera and the focal axis of the light source.
- $a$  is the distance between the focal axis of the camera and the lighting point.
- $D$  is the distance between the camera and the lighting point when this one is on the focal axis of the camera.

Thus, we have

$$d = D - \frac{a}{\tan \alpha}$$

However,  $\alpha$ ,  $a$  and  $D$  are not known yet, that is why a calibration phase is needed (see Figure 2.6). The first parameter,  $\alpha$ , is determined during the installation of the light source and the camera on the rover. Then, during the calibration, two steps can be identified. During the first one, a target is positioned such as the lighting point is on the center of the image recorded by the camera. Thus,  $D$  can be measured. During the second step, a target is positioned such as the lighting point is right on side (left or right) of the image recorded by the camera (see Figure 2.6). Therefore,  $a_0$  can be measured and we have

$$a = \frac{Na_0}{A_0}$$

with

- $N$  [*pixels*], the number of pixel between the center of the image recorded by the camera and the lighting point.
- $A_0$  [*pixels*], the number of pixel between the center of the image recorded by the camera and the lighting point during the calibration phase, that is to say, the half of the pixels of the width of the image.

Therefore, we have

$$d = D - \frac{Na_0}{\tan \alpha} \tag{2.2}$$

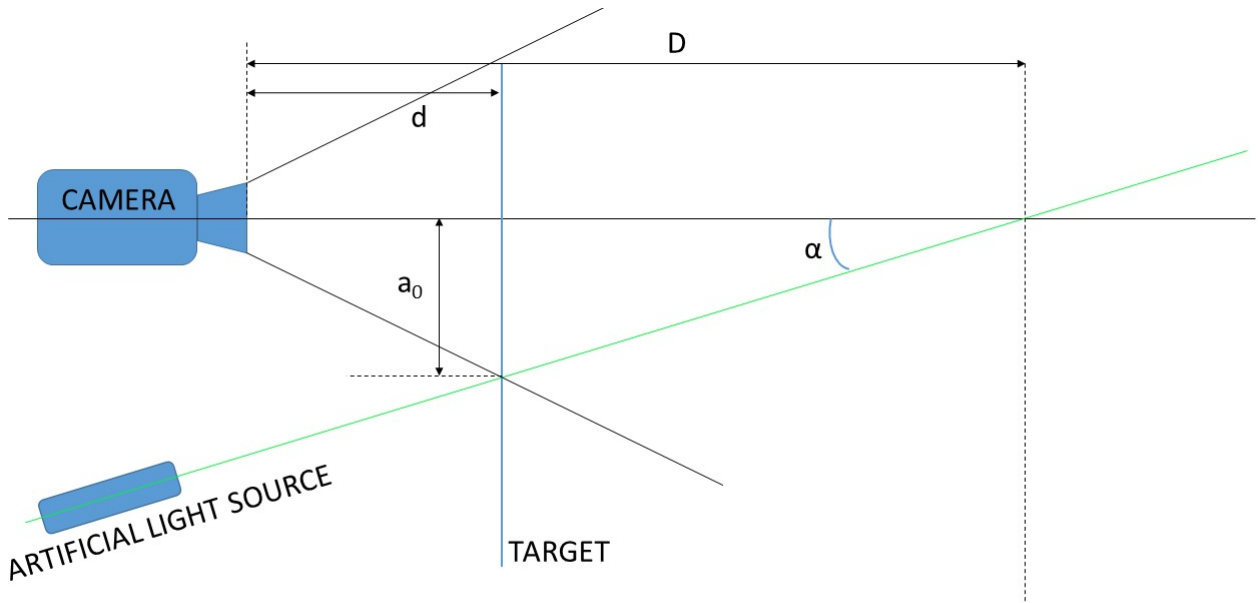


Figure 2.6: schema of the calibration

## 2.4 Image processing

In the following part of this report, the color detection will be used to distinguish color light points sent from a luminous source from the background, the Martian rocks. In order to implement this color detection, the HSV color model needs to be defined, as well as some morphological operations.

### 2.4.1 HSV Color System

HSV stands for Hue Saturation Value. It is a color system which allows the separation of the color components from the intensity, unlike RGB system. It is more intuitive to find a plain object by varying HSV parameters.

The Hue designates the color itself. As it can be seen on the figure 2.7, the color is determined by an angle between  $0^\circ$  and  $360^\circ$ . Red corresponds to  $0^\circ$ , green to  $120^\circ$  and blue to  $240^\circ$ . OpenCV range is 0-180. Changing the Saturation will affect the intensity of the color. A low value indicates a dull color. The Value has an impact on the luminosity of the color. Decreasing this value makes the color darker. The S and V are varying between 0 and 1 but the OpenCV range is 0-255.



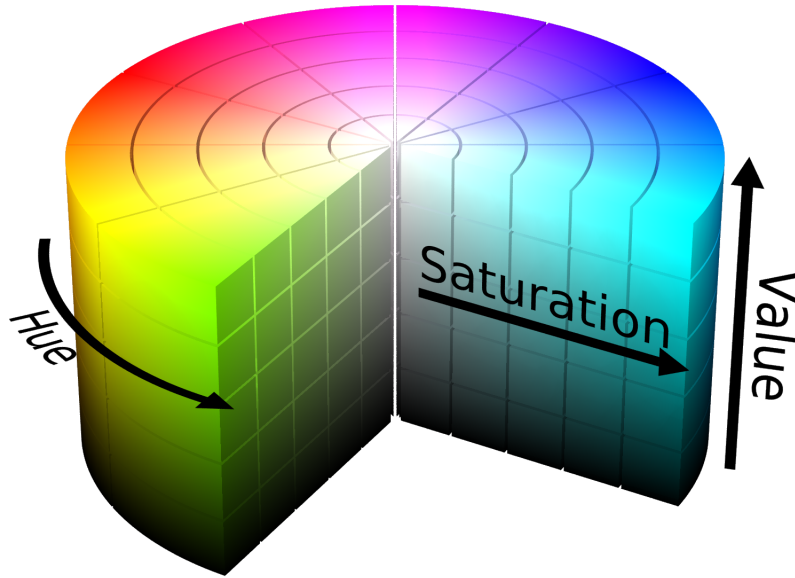


Figure 2.7: HSV diagram [9]

### 2.4.2 Morphological Operations [1]

The morphological operations on a binary image consists of applying a structuring element to each pixel of the object parts to reshape them. Two basic operations will be used later on and are explained here: the erosion and the dilation. Detailed diagram of the erosion and dilation can be found below (figures 2.8 and 2.9). It should be noticed that for more legibility, the background is in white and the object in color. It will however be assumed that the pixels of the object have a value superior to the background.

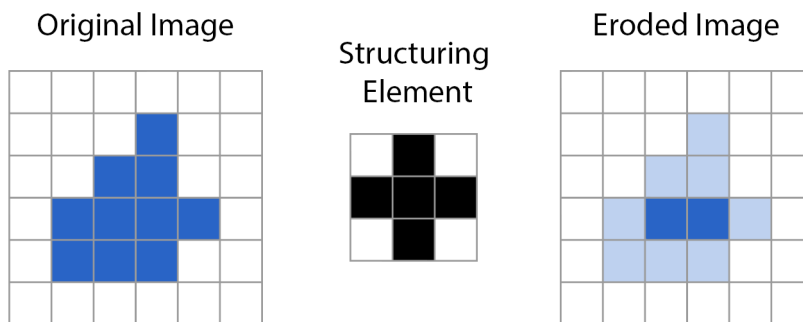


Figure 2.8: Erosion principle

#### 2.4.2.1 Erosion

This transformation is similar to the logic gate AND. The structuring element or kernel is moved along the image and the minimal pixel value is set as the new

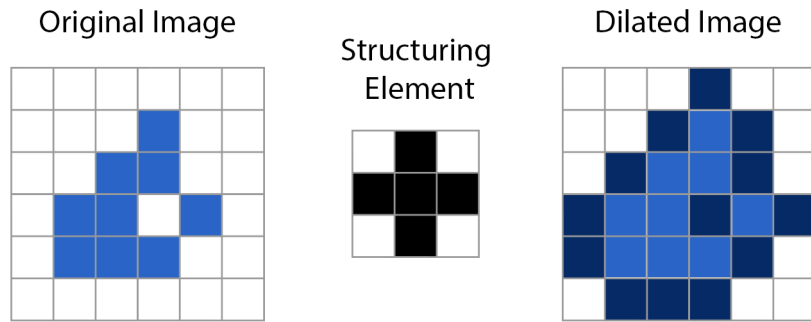


Figure 2.9: Dilation principle

value of the anchor point, in the figure, the center of the structuring element. This means that if all the points of the kernel are on an object (a white object on a black background), the anchor point will keep its value. On the contrary, if any element of the kernel is out of the object, the center point will become part of the background. The erosion is useful to separate two objects connected and to remove objects which are smaller than the size of the structuring element (noise).

#### 2.4.2.2 Dilation

The dilation is the opposite transformation of the erosion. It corresponds to the OR. If one element of the kernel is on the object (which is still assumed to have the maximal value for its pixel), the anchor point will be set to this value and thus be turned into a part of the object. This operation permits to fill holes in an object, to increase the size of an object and to link objects which are closer than the size of the structuring element.

#### 2.4.2.3 Opening

When combined, first by operating an erosion and then a dilation, the transformation is called an opening. The inverse operation is the closing. An opening could be convenient to separate luminous points which are connected and to then increase their size, lessen by the erosion.

## Part 3

# Development

### 3.1 Scene Analysis

In order to design the camera and find its characteristics, a scene analysis have to be carried out. Our study is based on the MER (Mars Exploration Rover) cameras properties [5]. To begin with, we choose an image sensor.

#### 3.1.1 CCD

The Charge Coupled Device (CCD) is commonly more sensitive to light than its counterpart, the CMOS (Complementary Metal Oxide Semiconductor). Moreover, in the near infrared CCD appears to have a better response. Since Mars has a reddish color, it seems more accurate to select the CCD detector.

As scientists will need to discern the details of rocks, the resolution should be around the megapixel. Taking into account the cost, which will increase with the resolution, and the time of computation for an image with too many pixels,  $1024 \times 1024$  seems to be an acceptable compromise.

Finally, the last element to consider is the pixel size. A trade-off have to be found between having a higher resolution (smaller pixels) and more sensitivity (larger pixels). All the camera of the MER mission were conceived with a pixel size of  $12 \times 12 \mu m$  for a resolution of  $1024 \times 1024$ . It was decided to comply with that value.

For the next parts of this report, we will use the data sheet of the FTT1010M CCD image sensor as a basis for our calculations which will require CCD details.

#### 3.1.2 Field of View

According to the book [2], the Field of View (FoV) “is the angle of the cone of directions encompassed by the scene that is being images”. This solid angle is

needed to compute the focal length the camera should have.

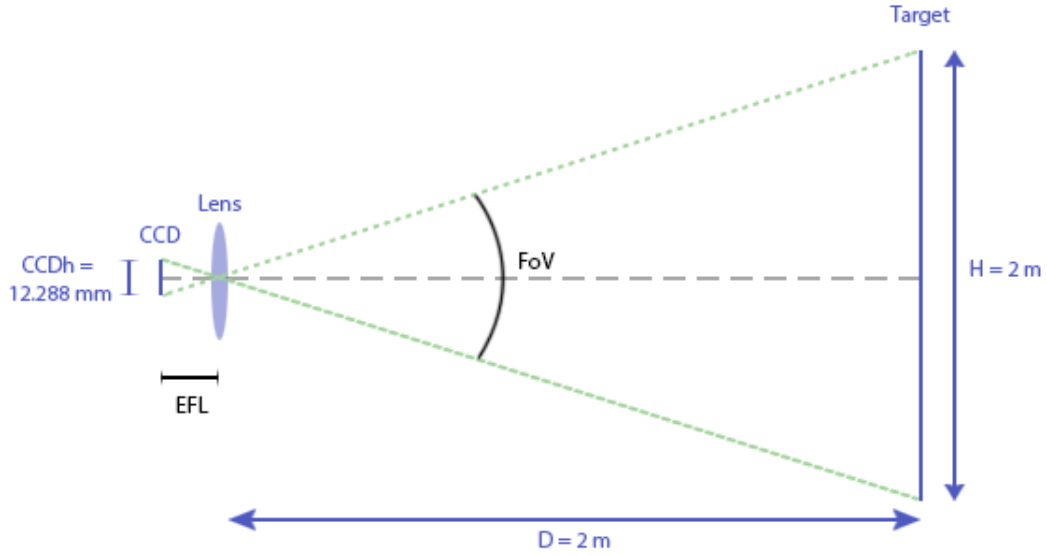


Figure 3.1: Field of View and Effective Focal Length

A simple relationship between the distance lens-target, the size of the target and the FoV can be deduced from the detailed diagram 3.1:

$$\tan\left(\frac{FoV}{2}\right) = \frac{1}{2} \times \frac{H}{D}$$

We derive and get

$$\frac{FoV}{2} = \text{atan}\left(\frac{1}{2} \times \frac{H}{D}\right)$$

Numerically, with our problem delimitation, the Field of View is equal to  $26.6^\circ \times 26.6^\circ$ .

### 3.1.3 Focal Length

Thanks to the previous diagram, the Effective Focal Length (EFL) can also be determined:

$$EFL = \frac{1}{2} \times \frac{CCDh}{\tan\left(\frac{FoV}{2}\right)} = 12.29 \text{ mm}$$

where  $CCDh$  is the image section of the CCD according to the data sheet.

In order to get the real focal length, we choose  $rf = 1 \text{ m}$  for the distance of

focus of the camera.

$$f = \frac{1}{\frac{1}{rf} + \frac{1}{EFL}} = 12.14 \text{ mm}$$

### 3.1.4 Aperture

To determine the diameter of the aperture, several criteria have to be accounted for. If the diameter is too small, the sharpness of the image will decrease due to the diffraction effect. In fact, at large aperture, the diffracted light is negligible compared to the total amount of light entering the system. On the other hand, we should also consider the Depth of Field (FoV). We need to insure that it is big enough to allow us to see the whole target on the image. The relationship between the DoF and the diameter is inversely proportional. That means that if we increase the diameter, we will lessen it. The Circle of Confusion (CoC), linked to the DoF is also a factor to take into consideration for the choice of the diameter. According to Wikipedia [8] It corresponds to “an optical spot caused by a cone of light rays from a lens not coming to a perfect focus when imaging a point source”. The smaller the CoC is, which corresponds to a better focus, the bigger is the DoF, and also the smaller is the diameter.

As the behaviour of the depth of field and of the circle of confusion runs counter to the diffraction one, a trade-off has to be found.

These formula are used to calculate the Diameter of Confusion (DoC) and the diffraction spot:

$$DoC = Dsr \cdot \frac{|r - rf|}{r} \cdot \frac{f}{rf - f}$$

where  $Dsr$  is the diameter of the aperture

$$DiffractionSpot = 2 \cdot EFL \cdot \tan(1.22 \cdot \frac{\lambda}{Dsr})$$

where  $\lambda$  is a wavelength of the sunlight

In the delimitations, it is assumed that the wavelengths of the sunlight belong to [400 800] nm. To settle on a diameter, the diameter of confusion and the diffraction spot were computed for diameters varying from 1 mm to 5 mm and wavelengths from 400 nm to 800 nm. The results are shown graphically in figure 3.2. As the diameter of confusion cannot be bigger than the height of a pixel, the line corresponding to 12  $\mu m$  was also added to the graphic. In order to have the best trade-off, that is to say all the curves under 12  $\mu m$ , we have chosen a effective

lens entrance aperture  $D_{sr}$  equal to  $1.9 \text{ mm}$ , corresponding to  $DoC = 0.0117 \text{ mm}$ .

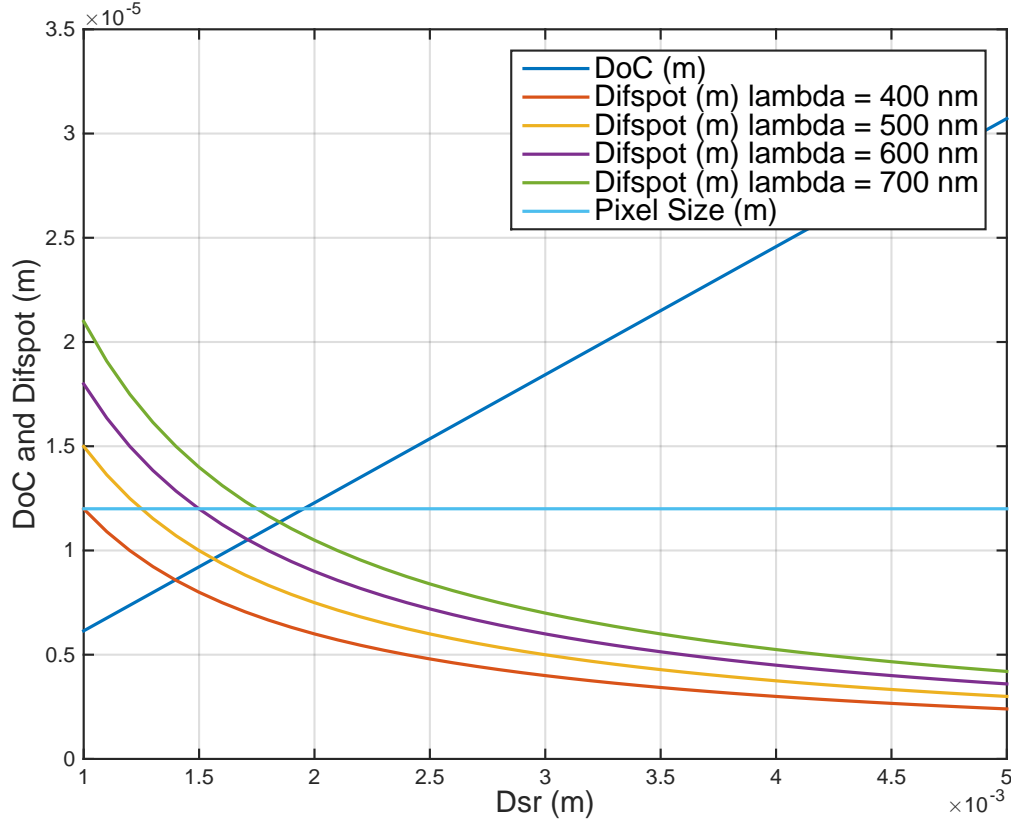


Figure 3.2: Diameter of confusion and diffraction spots as a function of the diameter

The circle of confusion can be deduced:

$$CoC = DoC \cdot m \quad \text{where } m = \frac{EFL}{rf}$$

and then:

$$DoF = \frac{2 \frac{f}{D_{sr}} CoC (m + 1)}{m^2 - \left(\frac{CoC}{D_{sr}}\right)^2} = 12.29 \text{ mm}$$

That means that the roughness of the rock analysed cannot be more than  $\frac{DoF}{2} = 6.14 \text{ mm}$  since we could not see the whole rock if not, and the 3D map will then be flawed.

### 3.1.5 Irradiance

First of all, the irradiance  $F$  of the light from the sun falling at the top of the

atmosphere of Mars can be calculated as following : Conservation of energy :

$$4\pi R_{\odot}^2 F_{\odot} = 4\pi R^2 F \quad (3.1)$$

with

$R_{\odot} = 6,956.10^8 \text{ m}$  : solar radius

$F_{\odot} = 6,45.10^7 \text{ W.m}^{-2}$  : energy flow of the surface of the sun

$R \in [2.06644, 2.49228].10^{11} \text{ m}$  : distance Mars-Sun (Aphelion and Perihelion)

$$F = F_{\odot} \left( \frac{R_{\odot}}{R} \right)^2 \in [502, 730] \text{ W/m}^2 \quad (3.2)$$

In this report, we will consider that the rover is working on a specific date and we will chose the one when  $R$  corresponds to the semi-major axis. In this case  $R = 2,27936.10^{11} \text{ km}$  and

$$F = 589 \text{ W/m}^2 \quad (3.3)$$

Moreover, we can assume that a part of the irradiance is absorbed by the atmosphere. Knowing that the atmosphere of Earth absorbs and scatters to space around 30% of the incident irradiance of the Sun[10], and knowing that the atmosphere of Mars is thinner than the one of the Earth (150 times less dense), we will postulate that 10% of the incident irradiance is absorbed. Thus, using (3.3) the actual irradiance  $F_a$  of the light from the sun falling on the surface of Mars is

$$F_a = \frac{90}{100} F = \frac{90 * 589}{100} = 530 \text{ W/m}^2 \quad (3.4)$$

However, this irradiance is the one of surface exposed perpendicular to the sun's beams. As Mars is a sphere, the projection need to be considered. Knowing that the weather is better into the northern hemisphere of Mars (2.1.2) and the fact that a latitude between 30 and 70 degrees is favored for a landing[3], we will assume that the rover has a latitude of  $50^\circ$ . This latitude corresponds to an angle of  $40^\circ$  between the surface of Mars and the sun's beams. Moreover, suppose that the rover stop working when this angle is inferior to  $10^\circ$ . Thus, the irradiance  $F_{50}$  at a latitude of  $50^\circ$  is

$$F_{50} = F_a \sin(\text{angleBeams}) \in [92, 341] \text{ W/m}^2 \quad (3.5)$$

with  $angleBeams = [10, 90 - latitude] = [10, 40]^\circ$ .

### 3.1.6 Target's Radiance

Considering the trajectory of the Sun into the sky of Mars and knowing that the rock target is more or less vertical to the surface of Mars, the angle  $\theta$  between the target's normal and the sun's beam is considered to be included in  $[10, 50]^\circ$ . In addition, in the optimal case (when all the optimal conditions are provided to have the maximal radiance), the BRDF of the surface of the target is assumed to be 90% Lambertian and 10% Glossy while in the worst case the BRDF will be only Lambertian. In this way, the radiance of the target  $R_T$  is

$$R_T = \begin{cases} \frac{F_{50}\alpha}{\pi} \cos \theta & \text{optimal case} \\ F_{50}\alpha(\frac{9}{10\pi} \cos \theta + \frac{1}{10}) & \text{worst case} \end{cases} \quad (3.6)$$

with

$\alpha \in [0.05, 0.45]$ , the albedo of the target

$\theta \in [10, 50]^\circ$ , the angle between the target's normal and the sun's beam

Thus,

$$R_T \in [1.44, 58.58] \text{ W/m}^2 \quad (3.7)$$

### 3.1.7 Target's Irradiance

Now, the irradiance of the target  $I_T$  can be calculated with

$$I_T = R_T \frac{\pi}{4} \left( \frac{Dsr}{EFL} \right)^2 \cos(\alpha_{CT})^4 \quad (3.8)$$

with

$\alpha_{CT}$  the angle between the normal of the target and the axis of the camera

$Dsr$  the effective lens entrance aperture

$EFL$  the focal length



However, knowing that the camera is supposed to be right in front of the target, we have

$$\alpha_{CT} = 0$$

And according to (3.8), (3.7), 3.1.4 and 3.1.3, we have

$$I_T \in [0.0271, 1.1000] \text{ W/m}^2 \quad (3.9)$$

Finally, the luminous power from the target to the camera per pixel  $W_{lum}$  is

$$W_{lum} = I_T P_s \quad (3.10)$$

with

$$P_s = 12.10^{-6} \times 12.10^{-6} \text{ m}^2, \text{ the pixel size of the CCD}$$

According to (3.9)

$$W_{lum} \in [3.900, 158.40].10^{-10} \text{ W/pixel} \quad (3.11)$$

### 3.1.8 Light Source Irradiance

Now, the luminous power of the light toward the CCD from the light source reflected by the target  $W_{LED}$  needs to be determined. First, the luminous power of each point  $W_{dot}$  projected by the source is

$$W_{dot} = \frac{LFLLed.LFGLed.P_{LED}}{N_{point}} = 4,4960.10^{-04} \text{ W} \quad (3.12)$$

with

$N_{points} = 10 \times 10 = 100$  points, the number of points projected on the target

$$P_{LED} = \frac{C_{LED}\Omega}{L_e} = 0.2997 \text{ W}, \text{ the power of the LED}$$

$C_{LED} = 84 \text{ cd}$ , the power of the LED in candella (Annex A)

$\Omega = 2\pi(1 - \cos \alpha) = 0.2141 \text{ sr}$ , the solid angle of the LED (Annex A)

$L_e = 60$ , the luminous efficiency of the LED

Then, the irradiance of a light point  $E_{point}$  is

$$E_{point} = \frac{W_{dot}}{A_{point}} = 71.5558 \text{ W/m}^2 \quad (3.13)$$

with  $A_{point} = 6,2832.10^{-6} \text{ m}^2$ , the surface of a point.

Finally,  $W_{LED}$  can be calculated following the same steps as in the previous part 3.1.7 except the fact that we have to consider an angle  $\theta_{Led} = 10^\circ$  between the light source and the normal of the target. Thus, the luminous power per pixel received by the CCD from the source light is  $W_{LED} = [3.033, 33.271].10^{-12} \text{ W/pixe}$

### 3.1.9 Signal/Noise Ratio

Three different cases will be studied. In the first one, we examine the case of a target illuminated by the sun without the use of laser, the second one considers the use of lasers by night and the last one, which is the case that we need to consider for our rover, study the use of lasers by daylight. In order to calculate the Signal/Noise ratio, the different noises need to be determined. Three will be taken into account: the readout noise, the dark current noise and the noise from the sun light.

The three different cases have the readout and the dark current noise in common which are given by the datasheet of the CCD B.

$$\delta_{readout} = \frac{RMS}{N_{pixel}} \quad (3.14)$$

$$= 2,3842.10^{-05} \text{ el/pixel} \quad (3.15)$$

$$\delta_{dark} = \left( 2,55.10^{15} N_{dc0} T_s (P_s.10^2)^2 T^{\frac{2}{3}} e^{-\frac{E_g}{2kT}} \right)^{\frac{1}{2}} \quad (3.16)$$

$$= 0.0067 \text{ el/pixel} \quad (3.17)$$

with

$RMS = 25 \text{ el}$ , the RMS readout noise B

$N_{pixel} = 1024 \times 1024 \text{ pixels}$ , the number of pixel of the CCDB

$N_{dc0} = 30 \text{ pA/cm}^2$ , the dark current level at 20°C B

$T_s = 0.1 \text{ s}$ , the shutter time

$P_s = 12.10^{-6} \text{ m}$ , the pixel size B

$T = 197 \text{ K}$ , the temperature

$$E_g = 1.1557 - \frac{7.10^{-4}T^2}{1108 + T}$$

$k = 8,62.10^{-5} \text{ eV/K}$ , the Boltzmann's constant

### 3.1.9.1 First case

In this case, the signal that needs to be considered is the sun light reflected by the target. Therefore, the readout and the dark current noises are the only two which need to be considered and the noise is

$$N = \sqrt{\delta_{readout}^2 + \delta_{dark}^2} = 0.0067 \text{ el/pixel} \quad (3.18)$$

Then, the number of photons per shutter time  $N_p$  corresponding o the radiance of the target is

$$N_p = \frac{1}{\lambda_{max} - \lambda_{min}} \int_{\lambda_{min}}^{\lambda_{max}} \frac{W_{lum}ts}{\frac{h.c}{\lambda}} d\lambda \in [1.177, 47.810].10^6 \text{ photons/pixel} \quad (3.19)$$

with

$ts = 0.1 \text{ s}$ , shutter time

$h = 6,6263.10^{-34} \text{ J.s}$ , Planck's constant

$c = 3.10^8 \text{ m/s}$ , velocity of light

$\lambda \in [400, 800] \text{ nm}$ , wavelength of the sunlight

The number of photons per pixel going to the lens  $N_{CCD}$  is

$$N_{CCD} = \frac{\pi \left(\frac{D_{sr}}{2}\right)^2}{2\pi(r)^2} N_p \in [0.1328, 5.3936] \text{ photons/pixel} \quad (3.20)$$

with  $r = 2 \text{ m}$ , the distance between the camera and the target

The number of photons per pixel to the lens registered by the CCD  $Nen_{CCD}$  is

$$Nen_{CCD} = N_{CCD} \int_{\lambda_{min}}^{\lambda_{max}} CCDqe(\lambda).alphaLens(\lambda) d\lambda \in [0.0208, 0.8457] \text{ photons/pixel} \quad (3.21)$$

with

$CCDqe$ , the quantum efficiency of the CCD 2.3

$alphaLens$ , the pass band efficiency of the lens

Finally, according to (3.18) and (3.21) we obtain the Signal/Noise ratio

$$\frac{S}{N} = \frac{Nen_{CCD}}{N} = [3.1, 126.8] \quad (3.22)$$

Knowing that, 100 is a really great Signal/Noise ratio, we can conclude that the system could record images of satisfactory or high quality the most of the time. However, if the different poor conditions accumulate, the quality of the image will greatly decrease.

### 3.1.9.2 Second case

In this case, the signal that needs to be considered is the light of the pseudo laser reflected by the target. Therefore, the noise is still the same as in the first case. Proceeding in the same way as into the first case 3.1.9.1 but considering only the wavelength of the LED( $520.10^{-9} \text{ m}$ ), the number of photons per pixel from the artificial light source going toward the CCD is  $Nen_{LED} = [2.4556, 26.9410] \text{ photon/pixel}$ .

And the Signal/Noise ratio is given by

$$\frac{S}{N} = \frac{Nen_{LED}}{N} = [368, 4040] \quad (3.23)$$

It can be deduced from this  $SNR$  that the system light source plus camera would work perfectly by night. Indeed, the minimum of this ratio is 368 which is larger than 100, an excellent ratio. Working by night would be the best scenario but the day work needs to be considered.

### 3.1.9.3 Third case

In this case, the current case, it will be determined if the artificial light source is powerful enough to outshine the sunlight. Thus, the sunlight is now considered as a noise, the shot noise.

$$N = \sqrt{\delta_{readout}^2 + \delta_{dark}^2 + \delta_{shot}^2} = [0.0219, 0.8457] \text{ el / pixel} \quad \text{with } \delta_{shot} = nen_{CCD} \quad (3.24)$$

As the signal and the noise are ranges because of the different conditions possible, the  $SNR$  should be

$$SNR = \left[ \frac{S_{min}}{N_{max}}, \frac{S_{max}}{N_{min}} \right] \quad \text{with } S = Nen_{LED}$$

However, it can be noticed that one parameter, the albedo  $\alpha$ , is varying for both lights, the sun and the artificial light source. Indeed, if the target has an albedo  $\alpha_{min}$ , this albedo needs to be considered in both calculation of the  $Nen_{CCD}$  and  $Nen_{LED}$ . Therefore, the calculation of the  $SNR$  needs to take into account this correlation and we have

$$SNR = [32, 348] \quad (3.25)$$

It can be concluded that the artificial light system is powerful enough to outshine the sunlight. Moreover, the quality of the image of the points should have an excellent quality, which would permit the 3D mapping algorithm to work perfectly. Also, even if the worst conditions are gathered (minimum albedo, sunset), the  $SNR$  is still equal to 32, which is acceptable.

## 3.2 Image Processing

To carry out the 3D map of a Martian rock, the coordinates of the points which are projected by the LED on its surface need to be determined on the video stream of the camera. They are obtained by detecting the points thanks to their color, and

by applying the centroid algorithm to get their center. First, the color detection method will be addressed, before focusing on the centroiding.

### 3.2.1 Color Detection

To increase the robustness of the algorithm, the color of the light beams was chosen to have the maximum contrast with the color of the rock. Mars having a reddish color, a bright green light seemed adapted. Moreover, as it is explained in the scene analysis part, the CCD sensor is more sensitive to the wavelength corresponding to the green (around 520 nm). Thus, the color detection algorithm aims to find bright green spots in the camera video stream in real time. It is implemented in C with OpenCV library.

The image analysis is performed by extracting frames from the video stream. These images are processed very quickly, which allows a real time analysis. The details of the method employed are given below. For the explanation, the figures are obtained for the detection of a blue box, but the algorithm works similarly for green light beams.

To begin with, a low-pass filter is applied to the image to handle to smooth it and to reduce the noise. Once achieved, the image is converted from RGB to HSV (see Theory Section) in order to get a better control of the colors and intensities of the image pixels. The range of the HSV parameters can be determined to isolate the bright green pixels from the rest of the image. The equivalent hue is between  $60^\circ$  and  $180^\circ$ , taking a large scope to be sure to isolate the good color component. As the luminous points will be bright, the range of the saturation and the luminosity should be chosen around the upper values. To adjust the values, several trackbars are added to the image, see figure 3.3 and the modifications are made in real time. All the values under the threshold defined are irrelevant. Thus the pixels of the binary image which corresponds to the HSV thresholding are set to 1 (white) for the zone where the light beams are recognized and to 0 (black) for the background, the rest of the image. This image is then easier to deal with because it is only composed of two values, black and white. Erosions and dilations can be applied respectively to separate connected light beams and remove noise or to fill holes in the rays. The number of erosions and dilations are selected thanks to trackbars once again (figure 3.3) and they are computed with the OpenCV functions.

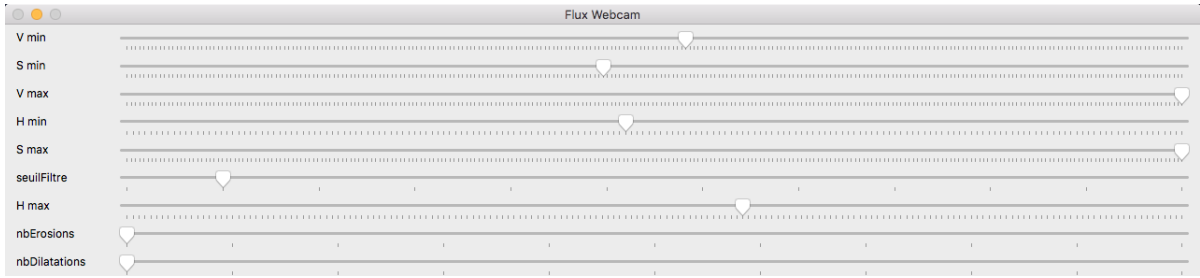


Figure 3.3: Trackbars for the threshold of the filter, the HSV parameters and the number of erosion and dilation

The calibration is carried out through the trackbars and the result is displayed on the video stream with the addition of contours to facilitate the tuning (figure 3.4). *cvFindContours* is used to search the contour of the light beams. The detection is based on the same principle that it has been seen during the exercises in the lab. The algorithm looks for the first pixel belonging to the beam and then follows the contour pixel by pixel. Once the threshold of the low-pass filter, the HSV values and the number of erosion and dilation are established, the calibration is completed.

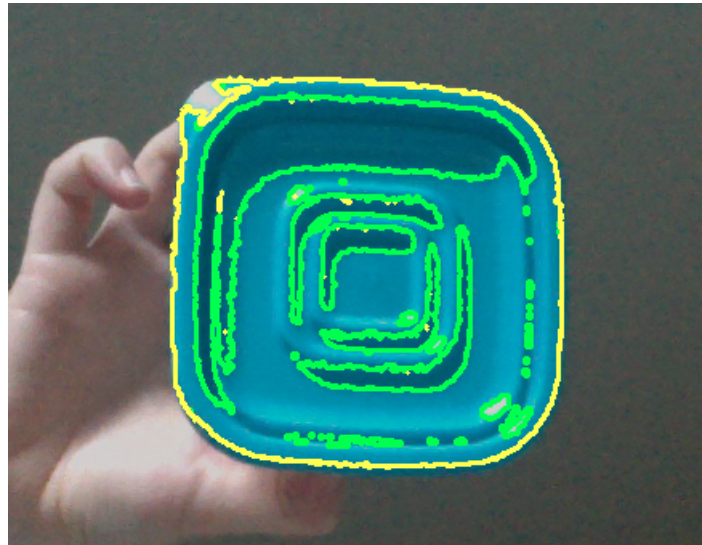


Figure 3.4: Contours of the detected object

In order to compute the centroid of the beams, it is needed to retrieve their intensity. To this end, the color detection should return an image with the light points in HSV color on a black background. To do so, the binary image is multiplied by the HSV image. The multiplication is explained by the pseudo code below.

```
function MULTIPLICATION(binary image, color image)
  for each pixel in the binary image do
    if the pixel value is white then
```

```

    pixelHSVColor ← the color of the pixel in the HSV image
    the color of the pixel in the final image ← pixelHSVColor
  else
    the color of the pixel in the final image ← black color
  end if
end for
end function

```

The final image obtained is shown figure 3.5.



Figure 3.5: Object detected in HSV color system on a black background

### 3.2.2 Centroiding

The 3D map can be performed with the coordinates of the light beams seen by the camera. They are determined by estimating the center of the spot, and to do so, the center of mass, also called the centroid needs to be calculated in the final image acquired by the color detection. In order to get it, a barycenter of the pixels belonging to the ray is carried out weighted by the intensity of the pixel (S value in HSV model).

$$x_c = \frac{\sum_x x \cdot I(x, y)}{\sum_x \sum_y I(x, y)} \quad (3.26)$$

$$y_c = \frac{\sum_y y \cdot I(x, y)}{\sum_x \sum_y I(x, y)} \quad (3.27)$$



Where  $x_c$  and  $y_c$  are the coordinates of the center of mass of the beam,  $x$  and  $y$  the coordinates of each pixel belonging to the beam and  $I$  their corresponding intensity.

The intensity of each pixel is obtained by splitting the canals of the image into three to retrieve an image with only the Saturation values. Then the formulas (3.26) and (3.27) are computed. A white cross is displayed on the centroid as it can be seen on the figure 3.5. The computation was performed for the same box as in the color detection but the algorithm can be adapted for several beams.

# Appendix A

## LED Properties

### Caractéristiques

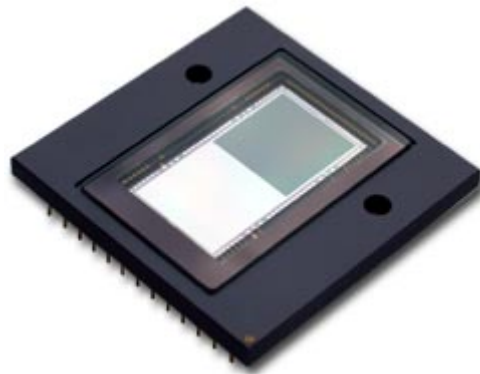
|                          |               |
|--------------------------|---------------|
| • Couleur                | Vert          |
| • Température de couleur | 525nm         |
| • Intensité Lumineuse    | 84000mcd      |
| • Ampérage Requis        | 20mA          |
| • Angle de Diffusion     | 30°           |
| • Consommation           | 220mW         |
| • Tension d'alimentation | 9.3 - 10.5V   |
| • Durée de vie estimée   | 80 000 Heures |

Figure A.1: LED Datasheet

# **Appendix B**

## **CCD Properties**

# DATA SHEET



## **FTT1010M**

### **1M Frame Transfer CCD Image Sensor**

Product specification

2007, April 17

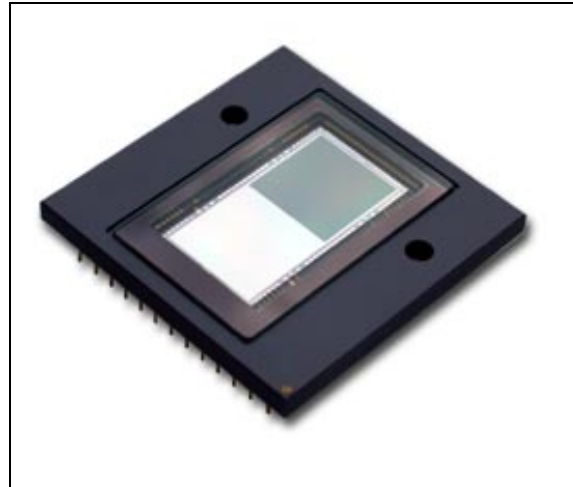
**DALSA**  
Professional Imaging



## 1M Frame Transfer CCD Image Sensor

FTT1010M

- 1-inch optical format
- 1M active pixels (1024H x 1024V)
- Progressive scan
- Excellent antiblooming
- Variable electronic shuttering
- Square pixel structure
- H and V binning
- 100% fill factor
- High dynamic range (>72dB)
- High sensitivity
- Low dark current and fixed pattern noise
- Low readout noise
- Data rate up to 2 x 40 MHz
- Mirrored and split readout
- RoHS compliant



## Description

The FTT1010M is a monochrome progressive-scan frame-transfer image sensor offering 1K x 1K pixels at 30 frames per second through a single output buffer. The combination of high speed and a high linear dynamic range (>12 true bits at room temperature without cooling) makes this device the perfect solution for high-end real time medical X-ray, scientific and industrial applications. A second output can either be used for mirrored images, or can be read out simultaneously with other output to double the frame rate. The device structure is shown in figure 1.

## Device structure

|                        |                                     |
|------------------------|-------------------------------------|
| Optical size:          | 12.288 mm (H) x 12.288 mm (V)       |
| Chip size:             | 14.572 mm (H) x 26.508 mm (V)       |
| Pixel size:            | 12 $\mu\text{m}$ x 12 $\mu\text{m}$ |
| Active pixels:         | 1024 (H) x 1024 (V)                 |
| Total no. of pixels:   | 1072 (H) x 1030 (V)                 |
| Optical black pixels:  | Left: 20    Right: 20               |
| Timing pixels:         | Left: 4    Right: 4                 |
| Dummy register pixels: | Left: 7    Right: 7                 |
| Optical black lines:   | Bottom: 6    Top: 6                 |

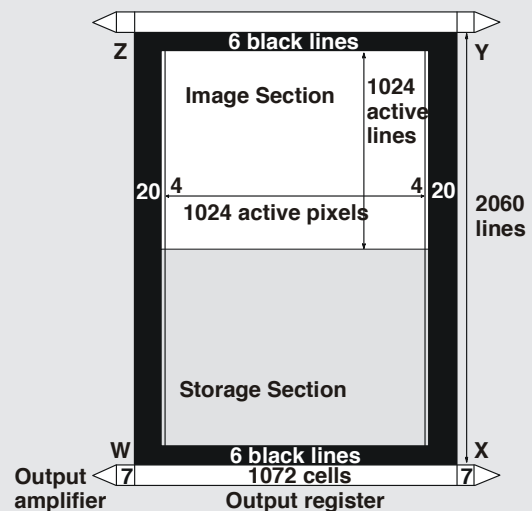


Figure 1 – Device Structure

# 1M Frame Transfer CCD Image Sensor

FTT1010M

## Architecture of the FTT1010M

The FTT1010M consists of a shielded storage section and an open image section. Both sections are electronically the same and have the same cell structure with the same properties. The only difference between two sections is the optical light shield.

The optical centres of all pixels in the image section form a square grid. The charge is generated and integrated in this section. Output registers are located below the storage section. The output amplifiers Y and Z are not used in Frame Transfer mode and should be connected as not-used amplifiers.

After the integration time, the charge collected in the image section is shifted to the storage section. The charge is read out line by line through the lower output register.

The left and the right half of each output register can be controlled independently. This enables either single or multiple readout.

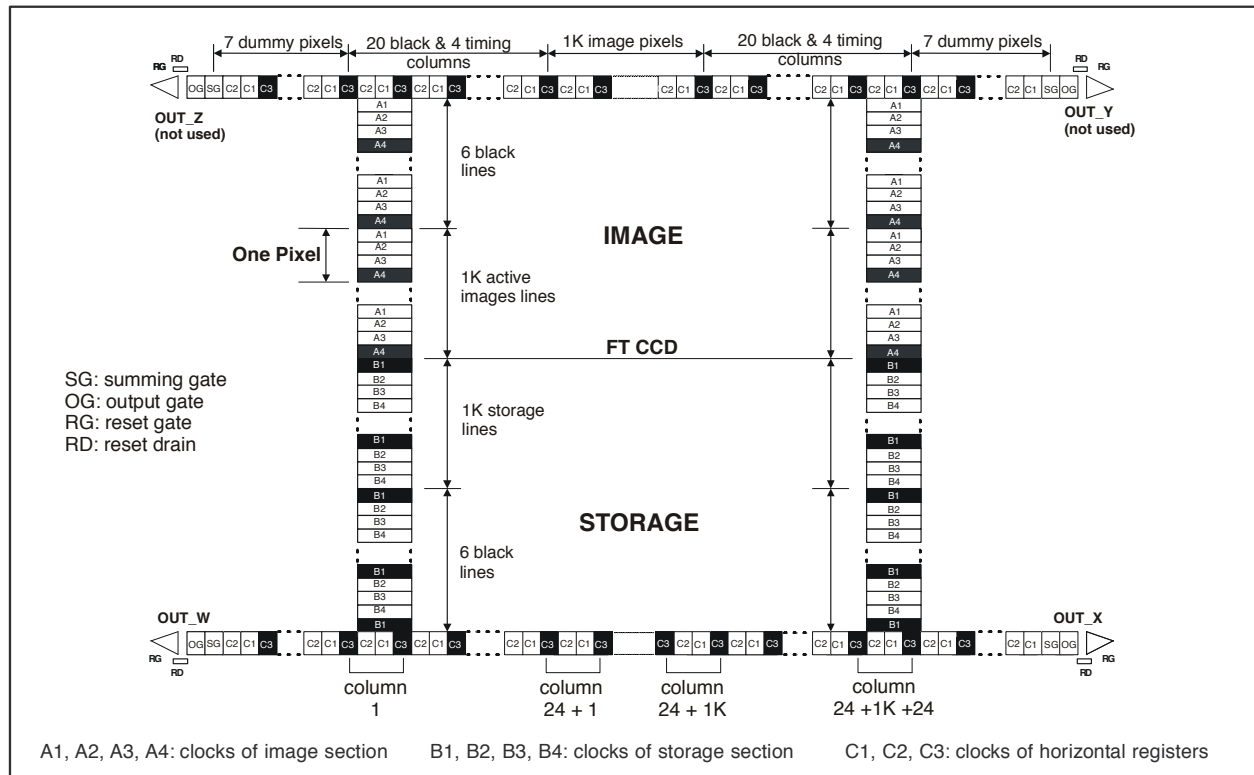
During vertical transport, the C3 gates separate the pixels in the register. The letters W, X, Y, and Z are used to define the four quadrants of the sensor. The central C3 gates of both registers are part of the W and Z quadrants of the sensor.

Both upper and lower registers can be used for vertical binning. Both registers also have a summing gate at each end that can be used for horizontal binning. Figure 2 shows the detailed internal structure.

| IMAGE SECTION                                   |                                 |
|---|---------------------------------|
| Image diagonal (active video only)              | 17.38 mm                        |
| Aspect ratio                                    | 1:1                             |
| Active image width x height                     | 12.288 x 12.288 mm <sup>2</sup> |
| Pixel width x height                            | 12 x 12 $\mu\text{m}^2$         |
| Fill factor                                     | 100%                            |
| Image clock pins                                | A1, A2, A3, A4                  |
| Capacity of each clock phase                    | 2.5nF per pin                   |
| Number of active lines                          | 1024                            |
| Number of black reference lines                 | 6                               |
| Total number of lines                           | 1030                            |
| Number of active pixels per line                | 1024                            |
| Number of overscan (timing) pixels per line     | 8 (2x4)                         |
| Number of black reference pixels per line       | 40 (2x20)                       |
| Total number of pixels per line                 | 1072                            |
| STORAGE SECTION                                 |                                 |
| Storage width x height                          | 12.864 x 12.360 mm <sup>2</sup> |
| Cell width x height                             | 12 x 12 $\mu\text{m}^2$         |
| Storage clock phases                            | B1, B2, B3, B4                  |
| Capacity of each clock phase                    | 2.5nF per pin                   |
| Number of cells per line                        | 1072                            |
| Number of lines                                 | 1030                            |
| OUTPUT REGISTERS                                |                                 |
| Output buffers (three-stage source follower)    | 4 (one on each corner)          |
| Number of registers                             | 2 (one above, one below)        |
| Number of dummy cells per register              | 14 (2x7)                        |
| Number of register cells per register           | 1072                            |
| Output register horizontal transport clock pins | C1, C2, C3                      |
| Capacity of each C-clock phase                  | 60pF per pin                    |
| Overlap capacity between neighbouring C-clocks  | 20pF                            |
| Output register Summing Gates                   | 4 pins (SG)                     |
| Capacity of each SG                             | 15pF                            |
| Reset Gate clock phases                         | 4 pins (RG)                     |
| Capacity of each RG                             | 15pF                            |

# 1M Frame Transfer CCD Image Sensor

FTT1010M



**Figure 2 - Detailed internal structure**

## 1M Frame Transfer CCD Image Sensor

FTT1010M

## Specifications

| ABSOLUTE MAXIMUM RATINGS <sup>1</sup>                                     |                        | MIN     | MAX         | UNIT    |          |
|---|------------------------|---------|-------------|---------|----------|
| GENERAL:  |                        |         |             |         |          |
| storage temperature   |                        | -55     | +80         |         | °C       |
| ambient temperature during operation                                      |                        | -40     | +60         |         | °C       |
| voltage between any two gates   |                        | -20     | +20         |         | V        |
| DC current through any clock (absolute value)                             |                        | -0.2    | +0.2        |         | μA       |
| OUT current (no short circuit protection)                                 |                        | 0       | 10          |         | mA       |
| VOLTAGES IN RELATION TO VPS:  |                        |         |             |         |          |
| VPS, SFD, RD  |                        | -0.5    | +30         |         | V        |
| VCS, SFS  |                        | -8      | +5          |         | V        |
| All other pins  |                        | -5      | +25         |         | V        |
| VOLTAGES IN RELATION TO VNS:  |                        |         |             |         |          |
| SFD, RD   |                        | -15     | +0.5        |         | V        |
| VCS, SFS, VPS   |                        | -30     | +0.5        |         | V        |
| All other pins  |                        | -30     | +0.5        |         | V        |
| DC CONDITIONS <sup>2,3</sup>  |                        | MIN [V] | TYPICAL [V] | MAX [V] | MAX [mA] |
| VNS <sup>4</sup>  | N substrate            | 20      | 24          | 28      | 15       |
| VPS   | P substrate            | 1       | 3           | 7       | 15       |
| SFD   | Source Follower Drain  | 16      | 20          | 24      | 4.5      |
| SFS   | Source Follower Source | -       | 0           | -       | 1        |
| VCS   | Current Source         | -5      | 0           | 3       | -        |
| OG  | Output Gate            | 4       | 6           | 8       | -        |
| RD  | Reset Drain            | 13      | 15.5        | 18      | -        |
| AC CLOCK LEVEL CONDITIONS <sup>2</sup>                                    |                        | MIN     | TYPICAL     | MAX     | UNIT     |
| IMAGE CLOCKS:   |                        |         |             |         |          |
| A-clock amplitude during integration and hold                             |                        | 8       | 10          |         | V        |
| A-clock amplitude during vertical transport (duty cycle=5/8) <sup>5</sup> |                        | 10      | 14          |         | V        |
| A-clock low level   |                        |         | 0           |         | V        |
| Charge Reset (CR) level on A-clock <sup>6</sup>                           |                        | -5      | -5          |         | V        |
| STORAGE CLOCKS:   |                        |         |             |         |          |
| B-clock amplitude during hold   |                        | 8       | 10          |         | V        |
| B-clock amplitude during vertical transport (duty cycle=5/8)              |                        | 10      | 14          |         | V        |
| OUTPUT REGISTER CLOCKS:   |                        |         |             |         |          |
| C-clock amplitude (duty cycle during hor. transport=3/6)                  |                        | 4.75    | 5           | 5.25    | V        |
| C-clock low level   |                        | 2       | 3.5         |         | V        |
| Summing Gate (SG) amplitude   |                        |         | 10          | 10      | V        |
| Summing Gate (SG) low level   |                        |         | 3.5         |         | V        |
| OTHER CLOCKS:   |                        |         |             |         |          |
| Reset Gate (RG) amplitude   |                        | 5       | 10          | 10      | V        |
| Reset Gate (RG) low level   |                        |         | 3           |         | V        |
| Charge Reset (CR) pulse on Nsub <sup>6</sup>                              |                        | 0       | 10          | 10      | V        |

<sup>1</sup> During Charge Reset it is allowed to exceed maximum rating levels (see note 5)<sup>2</sup> All voltages in relation to SFS<sup>3</sup> Power-up sequence: VNS, SFD, RD, VPS, others<sup>4</sup> To set the VNS voltage for optimal Vertical Antiblooming (VAB), it should be adjustable between minimum and maximum values<sup>5</sup> Three-level clock is preferred for maximum charge; the swing during vertical transport should be 4V higher than the voltage during integration  
A two level clock (typically 10V) can be used if a lower maximum charge handling capacity is allowed<sup>6</sup> Charge Reset can be achieved in two ways:

- The typical CR level is applied to all image clocks simultaneously (preferred).
- The typical A-clock low level is applied to all image clocks; for proper CR, an additional Charge Reset pulse on VNS is required. This will also affect the charge handling capacity in the storage areas.



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## Timing diagrams (for default operation)

| AC CHARACTERISTICS                           | MIN | TYPICAL | MAX    | UNIT    |
|--|-----|---------|--------|---------|
| Horizontal frequency ( $1/Tp$ ) <sup>1</sup> | 0   | 18      | 40     | MHz     |
| Vertical frequency                           | 0   | 450     | 1000   | kHz     |
| Charge Reset (CR) time                       | 2   | 20      |        | $\mu s$ |
| Rise and fall times: image clocks (A)        | 10  | 20      |        | ns      |
| storage clocks (B)                           | 10  | 20      |        | ns      |
| register clocks (C) <sup>2</sup>             | 3   | 5       | 1/6 Tp | ns      |
| summing gate (SG)                            | 3   | 5       | 1/6 Tp | ns      |
| reset gate (RG)                              | 3   | 5       | 1/6 Tp | ns      |

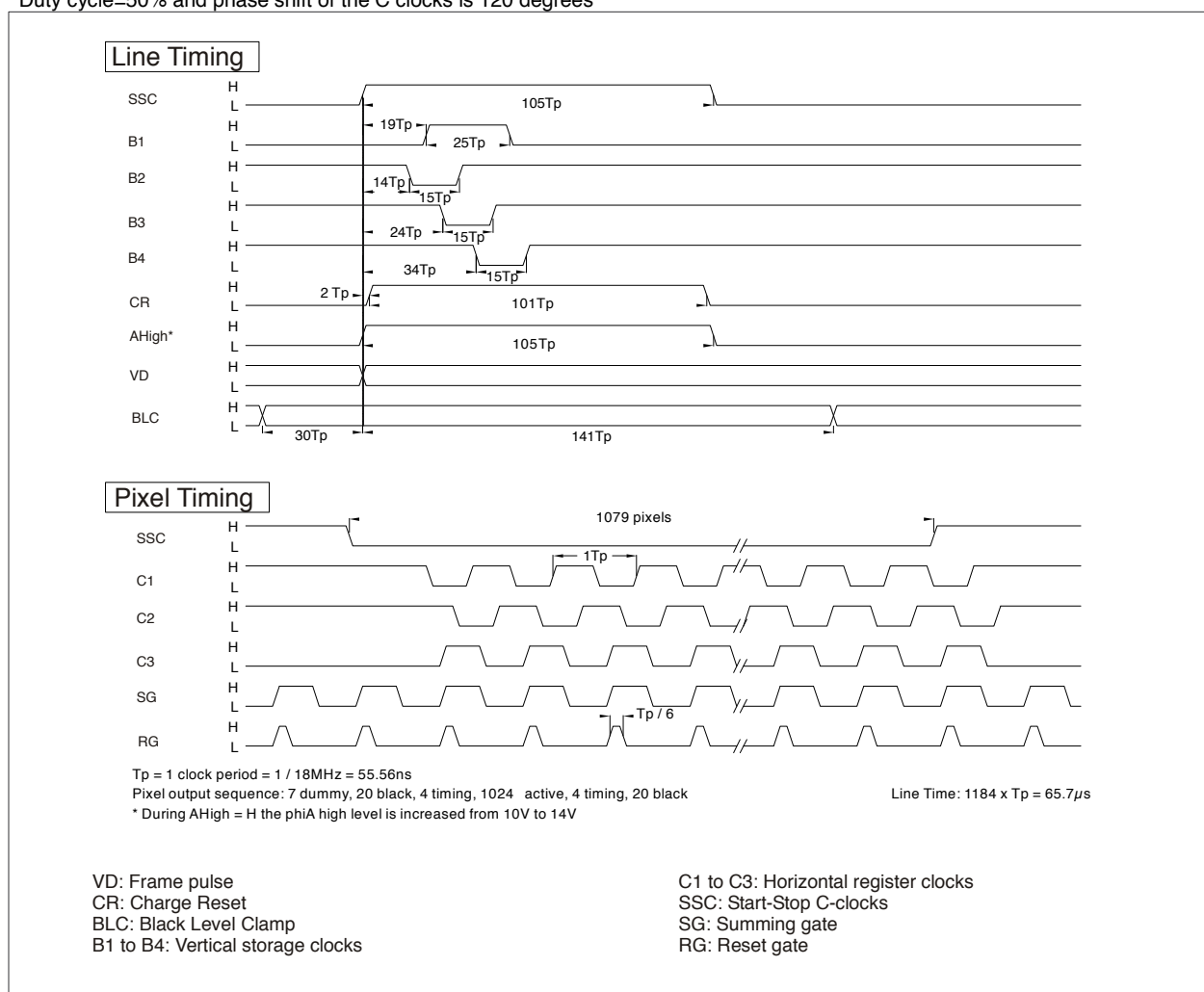
<sup>1</sup> TP=1 clock period<sup>2</sup> Duty cycle=50% and phase shift of the C clocks is 120 degrees

Figure 3 - Line and pixel timing diagrams

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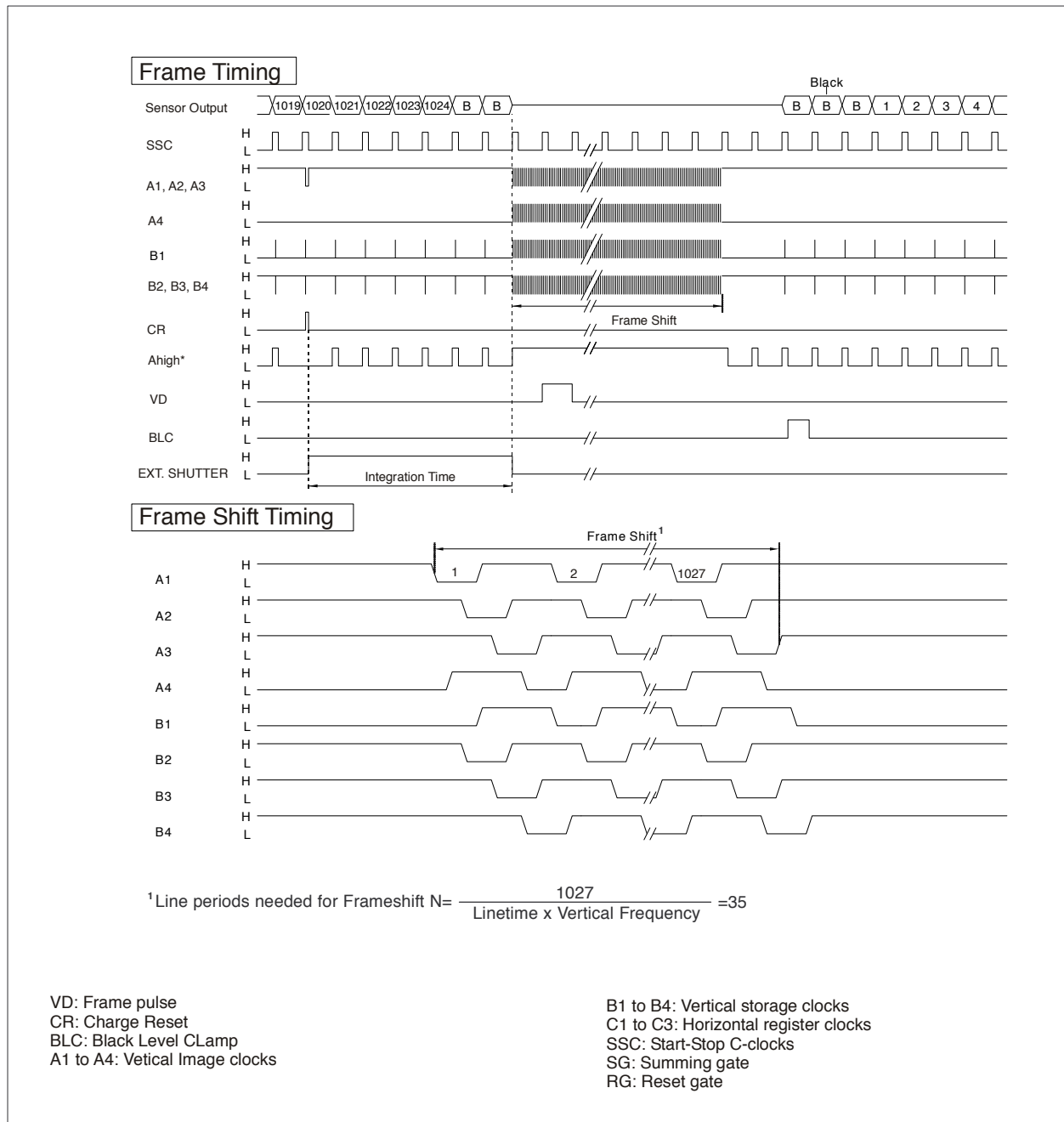


Figure 4 - Frame timing diagrams

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## Line timing

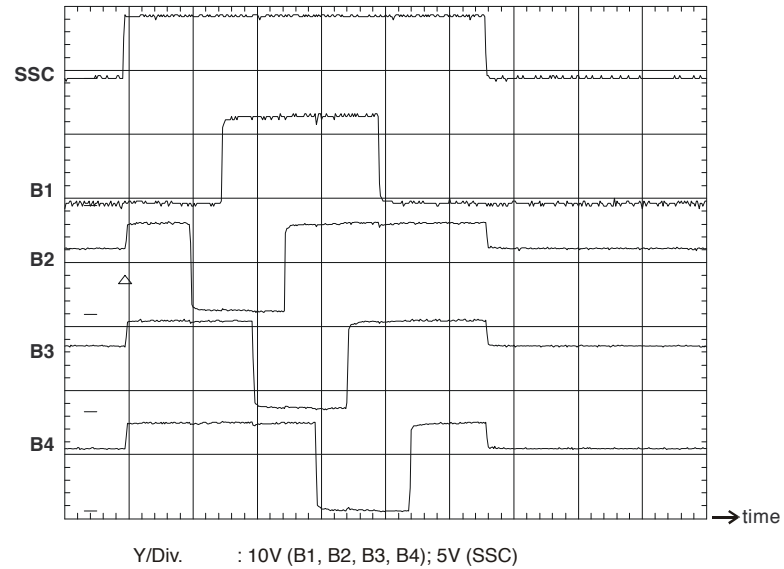


Figure 5 - Vertical readout

## Pixel timing

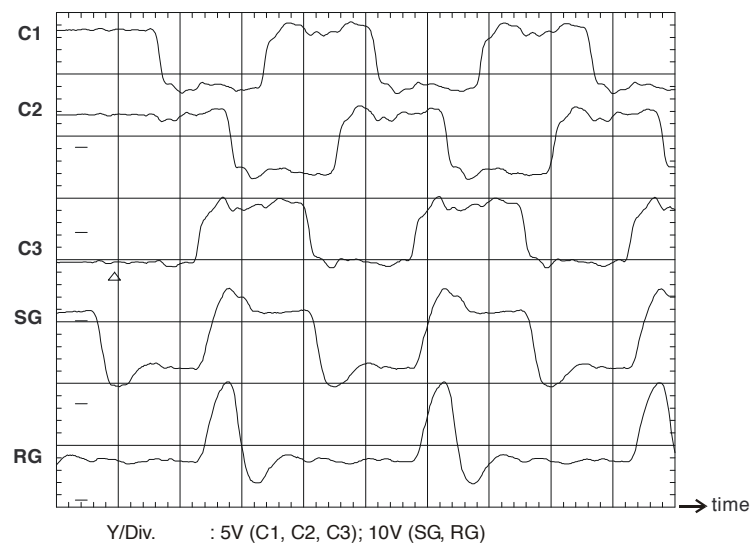


Figure 6 - Start horizontal readout

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**Performance**

The test conditions for the performance characteristics are as follows:

- All values are measured using typical operating conditions.
- VNS is adjusted as low as possible while maintaining proper Vertical Antiblooming
- Sensor temperature=60°C (333K)
- Horizontal transport frequency=18MHz
- Vertical transport frequency=450kHz
- Integration time=10ms
- The light source is a lamp of 3200K in conjunction with neutral density filters and a 1.7mm thick BG40 infrared cut-off filter. For Linear Operation measurements, a temperature conversion filter (Melles Griot type no. 03FCG261, -120 mired, thickness: 2.5mm) is applied.

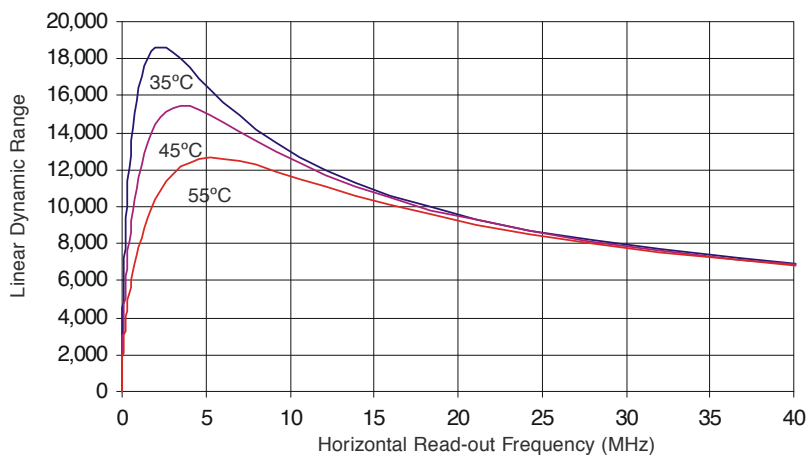
| LINEAR OPERATION                                   | MIN | TYPICAL  | MAX | UNIT      |
|--|-----|----------|-----|-----------|
| Charge Transfer Efficiency <sup>1</sup> vertical   |     | 0.999995 |     |           |
| Charge Transfer Efficiency <sup>1</sup> horizontal |     | 0.999999 |     |           |
| Image lag  |     |          | 0   | %         |
| Smear <sup>2</sup>                                 |     | -39      | 0   | dB        |
| Resolution (MTF) @ 42lp/mm                         | 65  |          |     | %         |
| Light sensitivity                                  | 180 | 250      |     | kel/lux*s |
| Low Pass Shading <sup>3</sup>                      |     |          | 2.5 | %         |
| Random Non-Uniformity (RNU) <sup>4</sup>           |     | 0.3      | 5   | %         |

<sup>1</sup>Charge Transfer Efficiency values are tested by evaluation and expressed as the value per gate transfer.

<sup>2</sup>Smear is defined as the ratio of 10% of the vertical transport time to the integration time. It indicates how visible a spot of 10% of the image height would become.

<sup>3</sup>Low Pass Shading is defined as the ratio of the one- $\sigma$  value of the pixel output distribution expressed as a percentage of the mean value output (low-pass image).

<sup>4</sup>RNU is defined as the ratio of the one- $\sigma$  value of the highpass image to the mean signal value at nominal light.



Linear dynamic range is defined as the ratio of  $Q_{lin}$  to read-out noise (the latter reduced by Correlated Double Sampling).

**Figure 7 - Typical Linear dynamic range vs. horizontal read-out frequency and sensor temperature**

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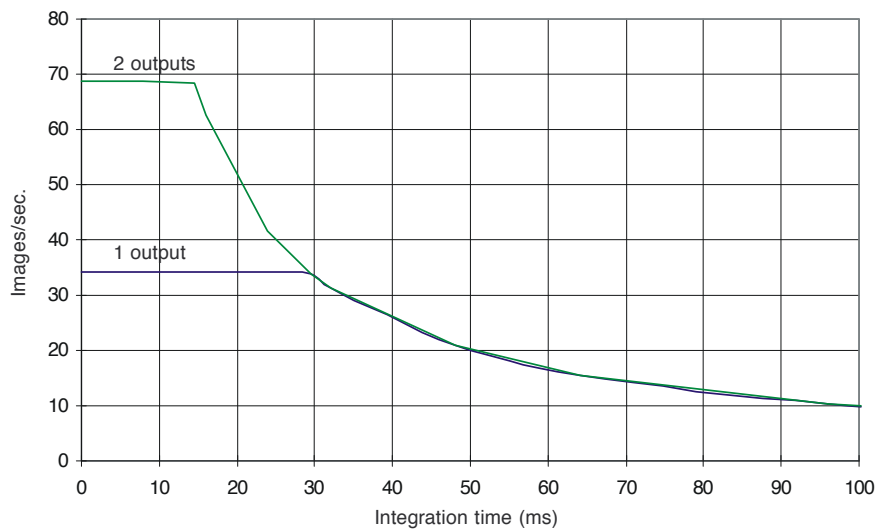


Figure 8 - Maximum number of images/second versus integration time

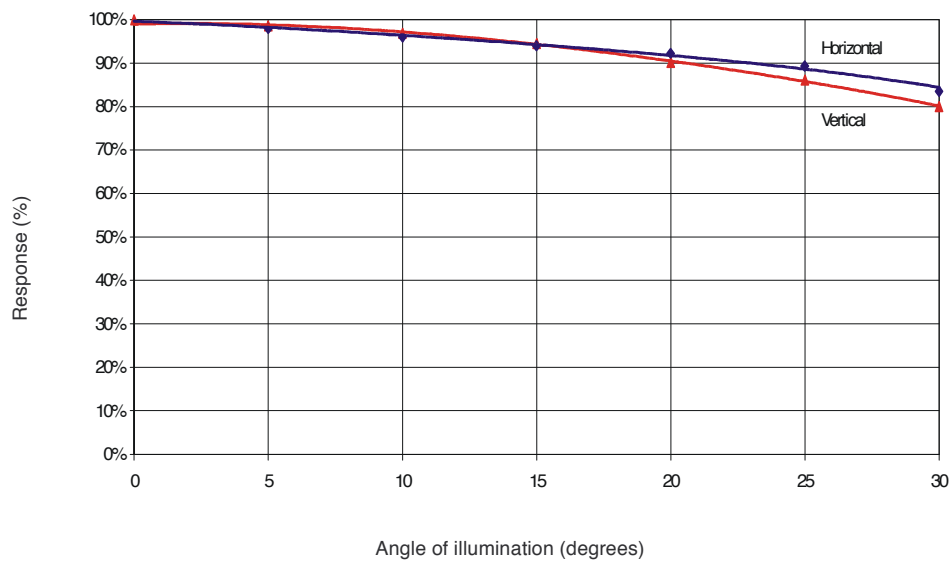


Figure 9 - Angular response versus angle of illumination

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1M Frame Transfer CCD Image Sensor

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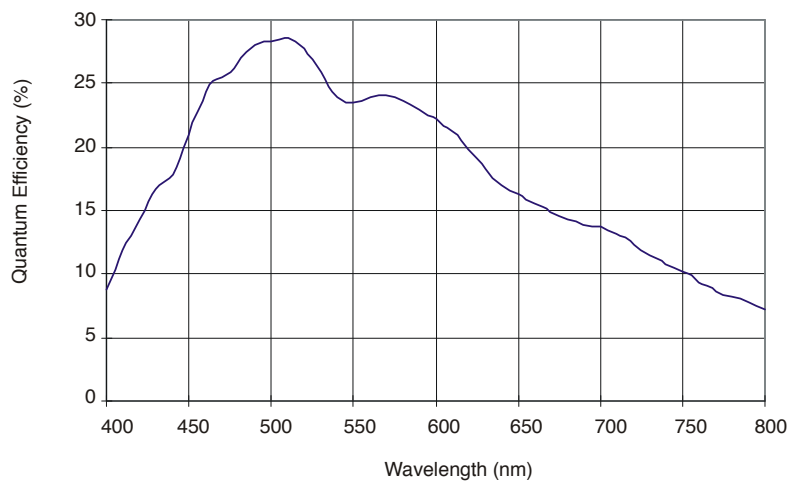


Figure 10 - Quantum efficiency versus wavelength

## 1M Frame Transfer CCD Image Sensor

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| LINEAR/SATURATION                                       | MIN | TYPICAL | MAX | UNIT         |
|---|-----|---------|-----|--------------|
| Full-well capacity saturation level (Qmax) <sup>1</sup> | 250 | 500     | 600 | kel          |
| Full-well capacity linear operation (Qlin) <sup>2</sup> | 200 | 350     |     | kel          |
| Charge handling capacity <sup>3</sup>                   |     | 600     |     | kel          |
| Overexposure <sup>4</sup> handling                      | 100 | 200     |     | x Qmax level |

<sup>1</sup>Qmax is determined from the low-pass filtered image.

<sup>2</sup>The linear full-well capacity Qlin is calculated from linearity test (see dynamic range). The evaluation test guarantees 97% linearity.

<sup>3</sup>Charge handling capacity is the largest charge packet that can be transported through the register and read-out through the output buffer.

<sup>4</sup>Overexposure over entire area while maintaining good Vertical Antiblooming (VAB). It is tested by measuring the dark line.

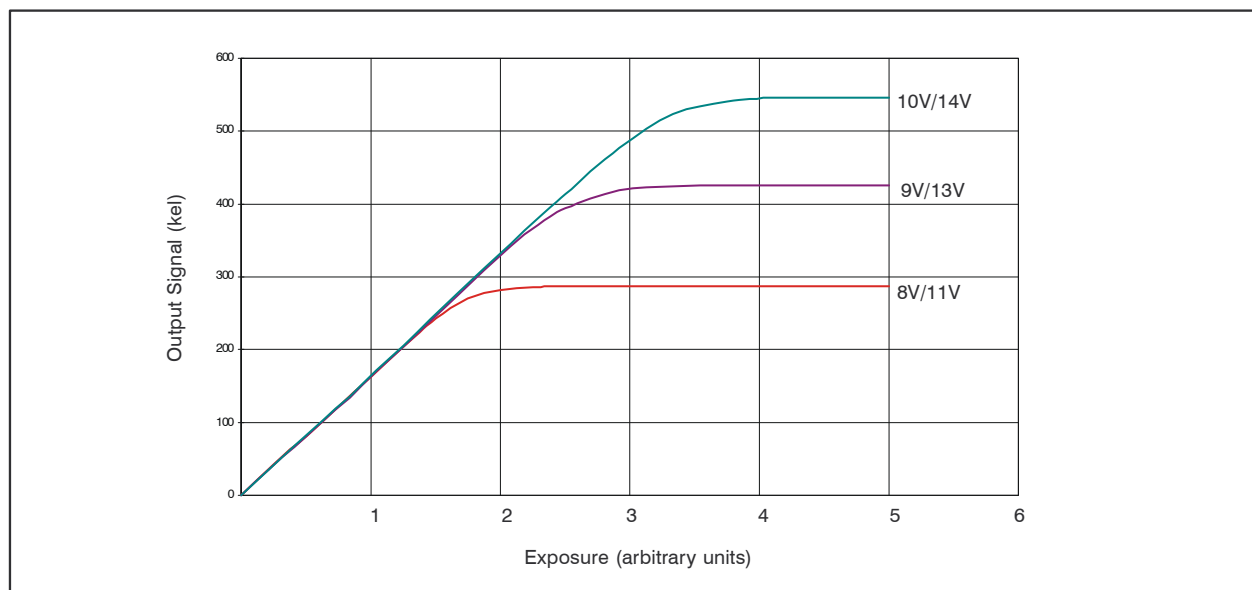


Figure 11 – Charge handling versus integration/transport voltage

## 1M Frame Transfer CCD Image Sensor

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| OUTPUT BUFFERS   | MIN | TYPICAL | MAX | UNIT                    |
|--|-----|---------|-----|-------------------------|
| Conversion factor  | 6   | 8       | 12  | $\mu\text{V}/\text{el}$ |
| Mutual conversion factor matching ( $\Delta\text{ACF}$ ) <sup>1</sup>                  |     | 0       | 2   | $\mu\text{V}/\text{el}$ |
| Supply current   |     | 4       |     | mA                      |
| Bandwidth  |     | 110     |     | MHz                     |
| Output impedance buffer ( $R_{\text{load}}=3.3\Omega$ , $C_{\text{load}}=2\text{pF}$ ) |     | 400     |     | $\Omega$                |

<sup>1</sup>Matching of the four outputs is specified as  $\Delta\text{ACF}$  with respect to reference measured at the operating point ( $Q_{\text{lin}}/2$ )

| DARK CONDITION                                | MIN | TYPICAL | MAX | UNIT                    |
|---|-----|---------|-----|-------------------------|
| Dark current level @ 20°C                     |     | 10      | 30  | $\text{pA}/\text{cm}^2$ |
| Dark current level @ 60°C                     |     | 0.3     | 0.6 | $\text{nA}/\text{cm}^2$ |
| Fixed Pattern Noise <sup>1</sup> (FPN) @ 60°C |     | 15      | 25  | el                      |
| RMS readout noise @ 9MHz bandwidth after CDS  |     | 25      | 30  | el                      |

<sup>1</sup>FPN is one- $\sigma$  value of the high-pass image.

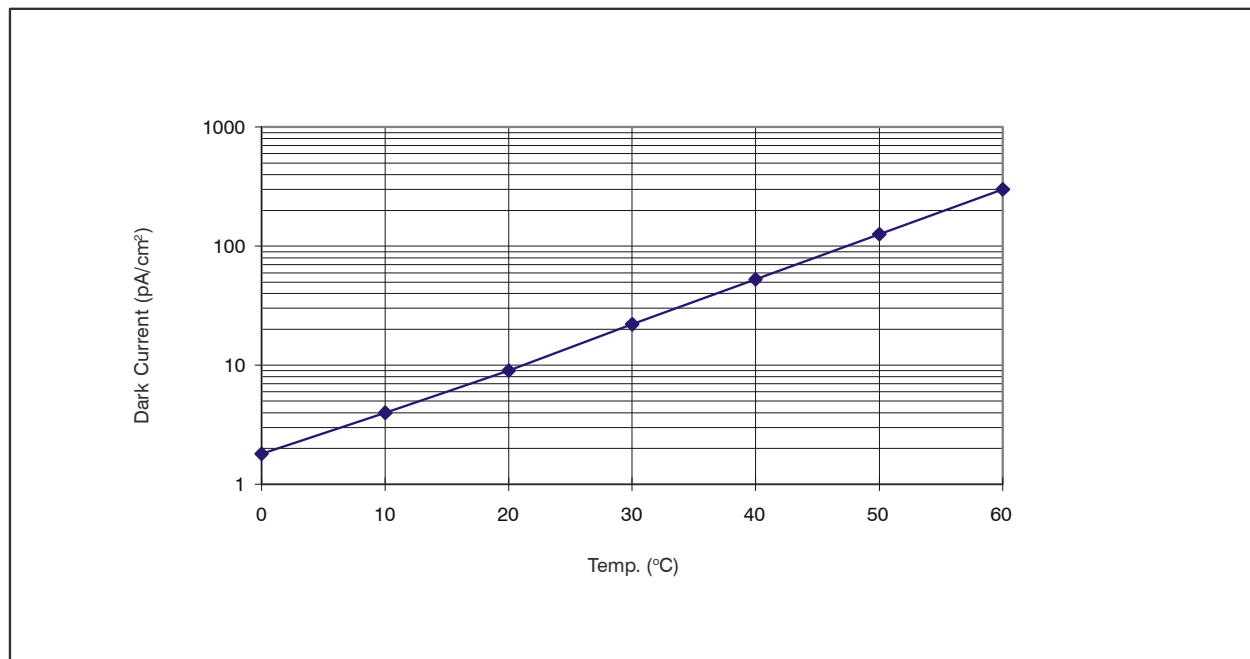


Figure 12 – Dark current versus temperature



# 1M Frame Transfer CCD Image Sensor

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## Application information

### *Current handling*

One of the purposes of VPS is to drain the holes that are generated during exposure of the sensor to light. Free electrons are either transported to the VRD connection and, if excessive (from overexposure), free electrons are drained to VNS. No current should flow into any VPS connection of the sensor. During high overexposure a total current of 10 to 15mA through all VPS connections together may be expected. The PNP emitter follower in the circuit diagram (figure 12) serves these current requirements.

VNS drains superfluous electrons as a result of overexposure. In other words, it only sinks current. During high overexposure, a total current of 10 to 15mA through all VNS connections together may be expected. The clamp circuit, consisting of the diode and electrolytic capacitor, enables the addition of a Charge Reset (CR) pulse on top of an otherwise stable VNS voltage. To protect the CCD, the current resulting from this pulse should be limited. This can be accomplished by designing a pulse generator with a rather high output impedance.

### *Decoupling of DC voltages*

All DC voltages (not VNS, which has additional CR pulses as described above) should be decoupled with a 100nF decoupling capacitor. This capacitor must be mounted as close as possible to the sensor pin. Further noise reduction (by bandwidth limiting) is achieved by the resistors in the connections between the sensor and its voltage supplies. The electrons that build up the charge packets that will reach the floating diffusions only add up to a small current, which will float through VRD. Therefore, a large series resistor in the VRD connection may be used.

### *Outputs*

To limit the on-chip power dissipation, the output buffers are designed with open source outputs. Outputs to be used should therefore be loaded with a current source or more simply with a resistance to GND. In order to prevent the output (which typically has an output impedance of about 400Ω) from bandwidth limitation as a result of capacitive loading, load the output with an emitter follower built from a high-frequency transistor. Mount the base of this transistor as close as possible to the sensor and keep the connection between the emitter and the next stage short. The CCD output buffer can easily be destroyed by ESD. By using this

emitter follower, this danger is suppressed; do NOT reintroduce this danger by measuring directly on the output pin of the sensor with an oscilloscope probe. Instead, measure on the output of the emitter follower. Slew rate limitation is avoided by avoiding a too-small quiescent current in the emitter follower; about 10mA should do the job. The collector of the emitter follower should be decoupled properly to suppress the Miller effect from the base-collector capacitance.

A CCD output load resistor of 3.3Ω typically results in a bandwidth of 110MHz. The bandwidth can be enlarged to about 130MHz by using a resistor of 2.2kΩ instead, which, however, also enlarges the on-chip power dissipation.

### *Device protection*

The output buffers of the FTT1010M are likely to be damaged if VPS rises above SFD or RD at any time. This danger is most realistic during power-on or power-off of the camera. The RD voltage should always be lower than the SFD voltage.

Never exceed the maximum output current. This may damage the device permanently. The maximum output current should be limited to 10mA. Be especially aware that the output buffers of these image sensors are very sensitive to ESD damage.

Because of the fact that our CCDs are built on an n-type substrate, we are dealing with some parasitic npn transistors. To avoid activation of these transistors during switch-on and switch-off of the camera, we recommend the application diagram of figure 12.

### *Unused sections*

To reduce power consumption, the following steps can be taken. Connect unused output register pins (C1...C3, SG, OG) and unused SFS pins to zero Volts.

### *More information*

Detailed application information is provided in the application note AN01 entitled "**Camera Electronics for the mK x nK CCD Image Sensor Family**".

# 1M Frame Transfer CCD Image Sensor

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## Device Handling

An image sensor is a MOS device which can be destroyed by electro-static discharge (ESD). Therefore, the device should be handled with care.

Always store the device with short-circuiting clamps or on conductive foam. Always switch off all electric signals when inserting or removing the sensor into or from a camera (the ESD protection in the CCD image sensor process is less effective than the ESD protection of standard CMOS circuits).

Being a high quality optical device, it is important that the cover glass remain undamaged. When handling the sensor, use fingercots.

When cleaning the glass we recommend using ethanol (or possibly water). Use of other liquids is strongly discouraged:

- if the cleaning liquid evaporates too quickly, rubbing is likely to cause ESD damage.
- the cover glass and its coating can be damaged by other liquids.

Rub the window carefully and slowly.

Dry rubbing of the window may cause electro-static charges or scratches which can destroy the device.

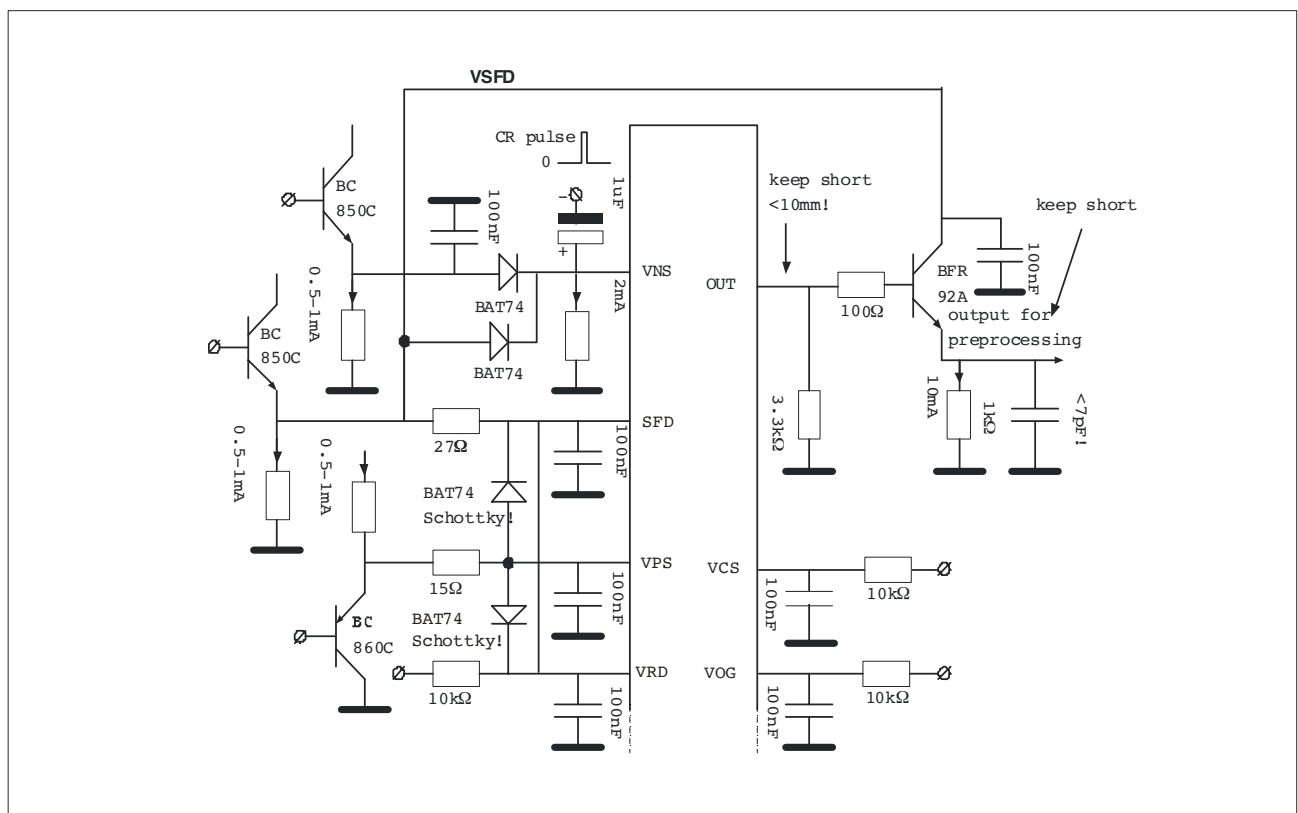


Figure 13- Application diagram

## 1M Frame Transfer CCD Image Sensor

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## Pin configuration

The FTT1010M is mounted in a Pin Grid Array (PGA) package with 80 pins in a 15x13 grid of 40.00 x 40.00 mm<sup>2</sup>. The position of pin A1 is marked with a gold dot on top of the

package. The image clock phases of quadrant W are internally connected to X, and the clock phases of Y are connected to Z.

| SYMBOL | LINEAR/SATURATION        | PIN # W | PIN # X | PIN # Y | PIN # Z |
|--------|--------------------------|---------|---------|---------|---------|
| VNS    | N substrate              | A12     | A3      | J2      | F11     |
| VNS    | N substrate              | D11     | B2      | F3      | H12     |
| VNS    | N substrate              | E11     | D3      | -       | J11     |
| VNS    | N substrate              | E12     | E2      | -       | -       |
| VNS    | N substrate              | -       | E3      | -       | -       |
| VPS    | P substrate              | C11     | C3      | G3      | G11     |
| SFD    | Source Follower Drain    | A13     | A1      | J1      | J13     |
| SFS    | Source Follower Source   | A10     | B5      | J4      | H9      |
| VCS    | Current Source           | A11     | A4      | J3      | J10     |
| OG     | Output Gate              | B13     | B1      | H1      | H13     |
| RD     | Reset Drain              | B12     | B3      | H2      | H11     |
| A1     | Image Clock (Phase 1)    | -       | -       | F1      | F13     |
| A2     | Image Clock (Phase 2)    | -       | -       | G2      | G12     |
| A3     | Image Clock (Phase 3)    | -       | -       | F2      | F12     |
| A4     | Image Clock (Phase 4)    | -       | -       | G1      | G13     |
| B1     | Storage Clock (Phase 1)  | D13     | D1      | -       | -       |
| B2     | Storage Clock (Phase 2)  | C12     | C2      | -       | -       |
| B3     | Storage Clock (Phase 3)  | D12     | D2      | -       | -       |
| B4     | Storage Clock (Phase 4)  | C13     | C1      | -       | -       |
| C1     | Register Clock (Phase 1) | B9      | A6      | H5      | J8      |
| C2     | Register Clock (Phase 2) | B8      | A7      | H6      | J7      |
| C3     | Register Clock (Phase 3) | A8      | B6      | J6      | H8      |
| SG     | Summing Gate             | B10     | A2      | H4      | J12     |
| RG     | Reset Gate               | A9      | A5      | J5      | J9      |
| OUT    | Output                   | B11     | B4      | H3      | J10     |
| NC     | Not Connected            | B7      | -       | H7      | -       |

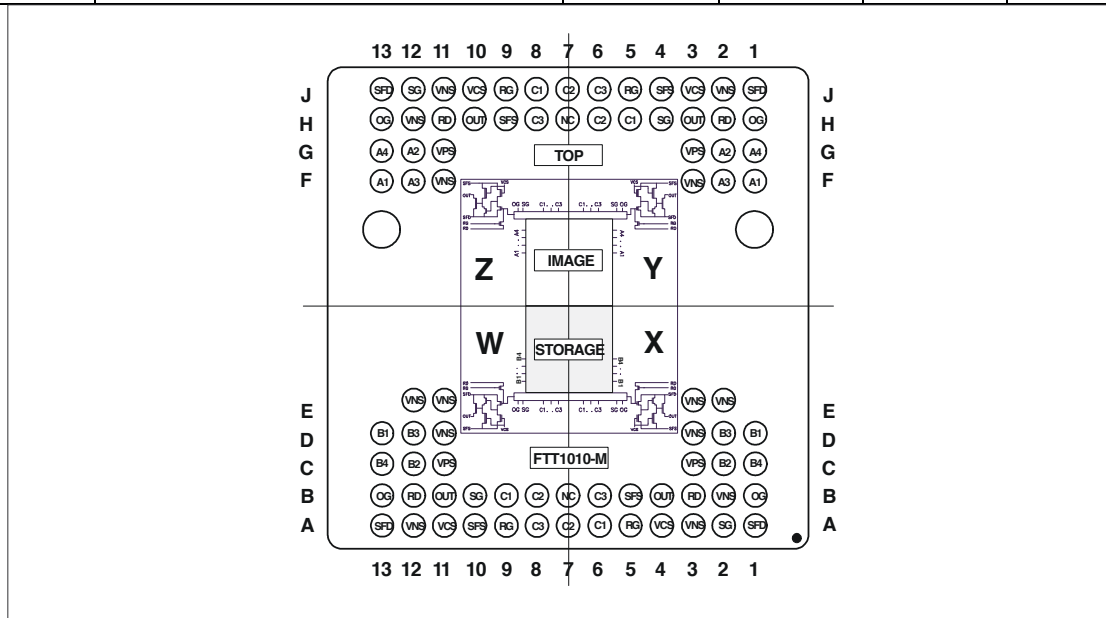


Figure 14 - Pin configuration (top view)

## 1M Frame Transfer CCD Image Sensor

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## Package information

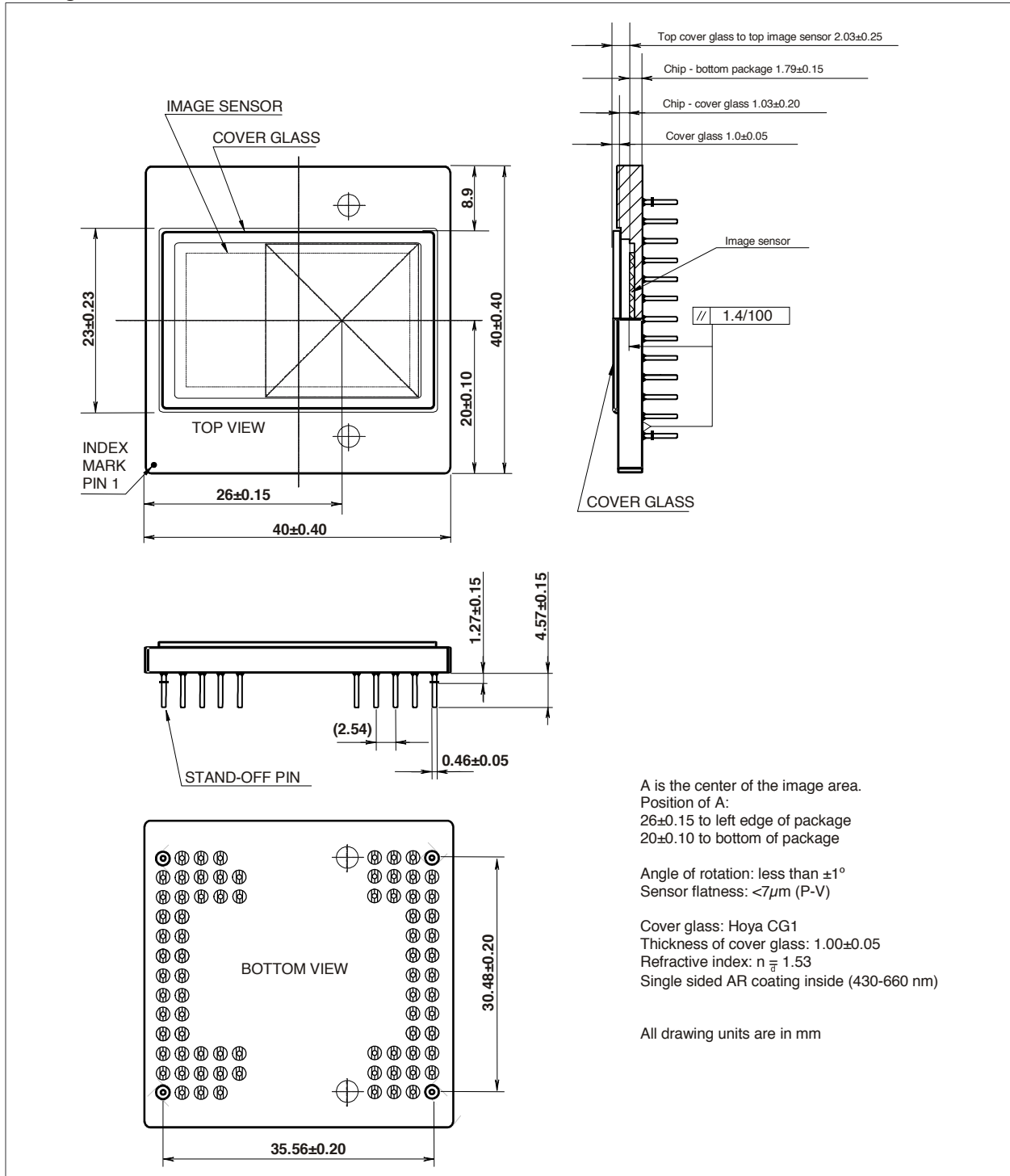


Figure 15– Mechanical drawing of the PGA package of the FTT1010M

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1M Frame Transfer CCD Image Sensor

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FTT1010M

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**Order codes**

The sensor can be ordered using the following code:

| FTT1010M sensors |                  |                |
|------------------|------------------|----------------|
| Description      | Quality Grade    | Order Code     |
| FTT1010M/TG      | Test grade       | 9922 157 35231 |
| FTT1010M/EG      | Economy grade    | 9922 157 35251 |
| FTT1010M/IG      | Industrial grade | 9922 157 35221 |
| FTT1010M/HG      | High grade       | 9922 157 35211 |

**Defect Specifications**

The CCD image sensor can be ordered in a specific quality grade. The grading is defined with the maximum amount of pixel defects, column defects, row defects and cluster defects, in both illuminated and non-illuminated conditions. For detailed grading information, please contact your local DALSA representative.

**For More Information**

For more detailed information on this and other products, contact your local rep or visit our Web site at <http://www.dalsa.com/sensors/products/products.asp>.

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[sales.sensors@dalsa.com](mailto:sales.sensors@dalsa.com)

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